



Microchannel Flow Boiling of CO₂

Applications to 2D and 3D Detector Cooling

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SLAC, Stanford: 9 Feb. 2011

(Based in part on Chapter 19 in Engineering Databook III at www.wlv.com)

Objectives and Topics to Be Covered:

- **CO₂ flow boiling is a promising cooling process for particle detectors.**
- **Overview applying to 2D and 3D detectors.**
- **Example: 3D-IC microchannel cooled stack from Swiss NSF Nano-Tera project CMOSAIIC.**
- **Single and multi-microchannel flow boiling videos**
- **Two-phase flow and heat transfer fundamentals.**
- **My CO₂ flow boiling/flow pattern map.**
- **Comparisons to the heat transfer model.**
- **Future plans for improvements.**



Four Books Authored by J.R. Thome

Thome, J.R. (1990). *ENHANCED BOILING HEAT TRANSFER*, Hemisphere Pub. Corp. (Taylor & Francis), New York, 13 chapters, 356 pages.

Collier, J.G. and Thome (1994: hardcover, 1996: paperback). *CONVECTIVE BOILING AND CONDENSATION*, 3rd Edition, Oxford University Press, Oxford, England, 12 chapters, 596 pages.

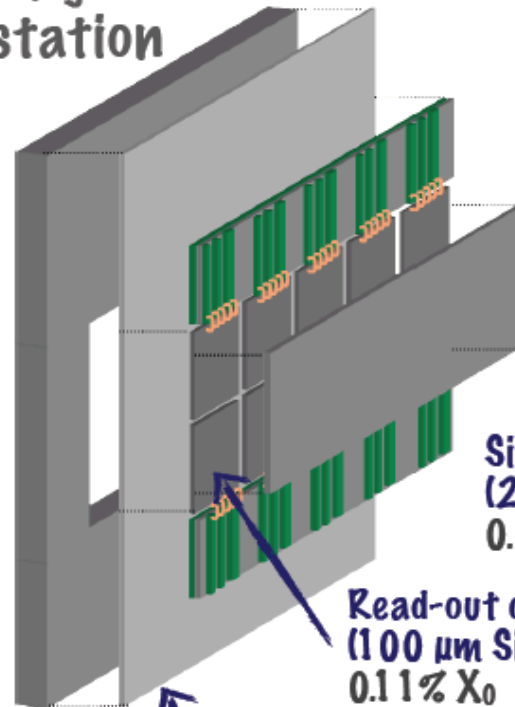
Thome, J.R. (2004). *WOLVERINE ENGINEERING DATABOOK III*. Web-based reference book with 21 chapters including one with over 200 two-phase flow videos, plus an *Excel calculator program* for numerous methods in book, updated in 2005, 2006, 2007, 2008, 2009, 2010. Available free at:
<http://www.wlv.com/products/databook/db3/DataBookIII.pdf>.

Poniewski, M.E. and Thome, J.R. (2008): *NUCLEATE BOILING ON MICRO-STRUCTURED SURFACES*, free e-book available at:

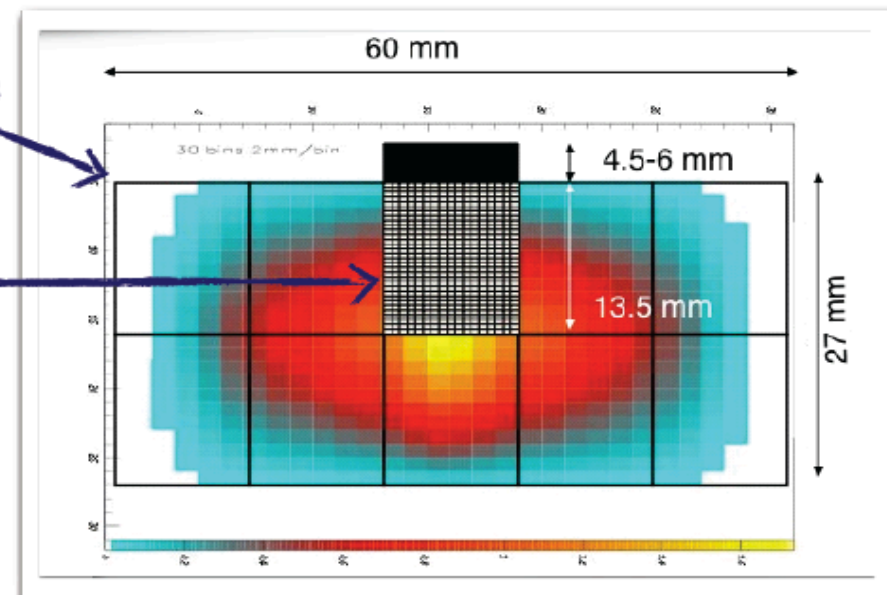
<http://www.htri-net.com/ePubs/epubs.htm> .

NA62-GTK cooling requirements

single GTK
station

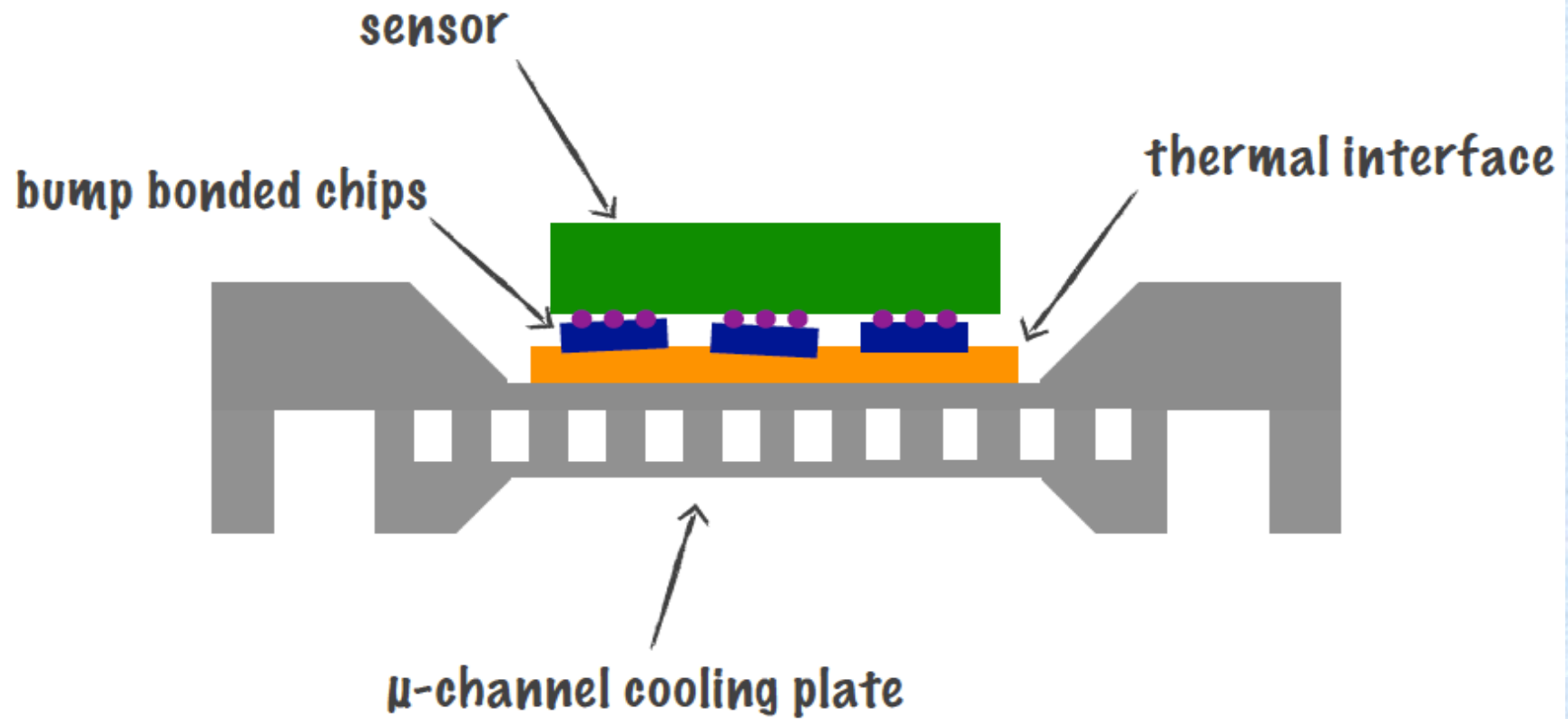


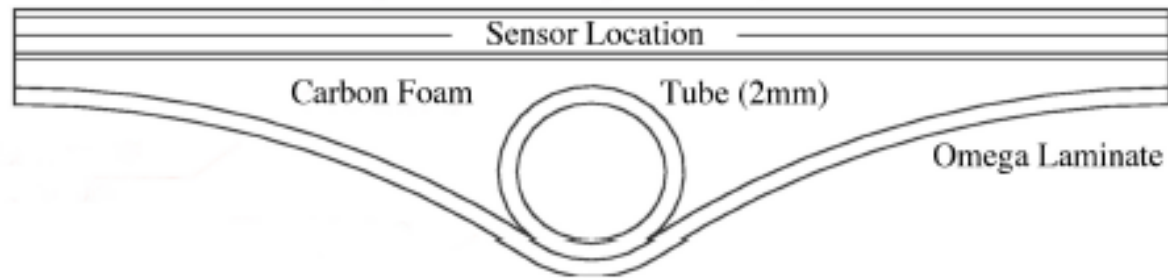
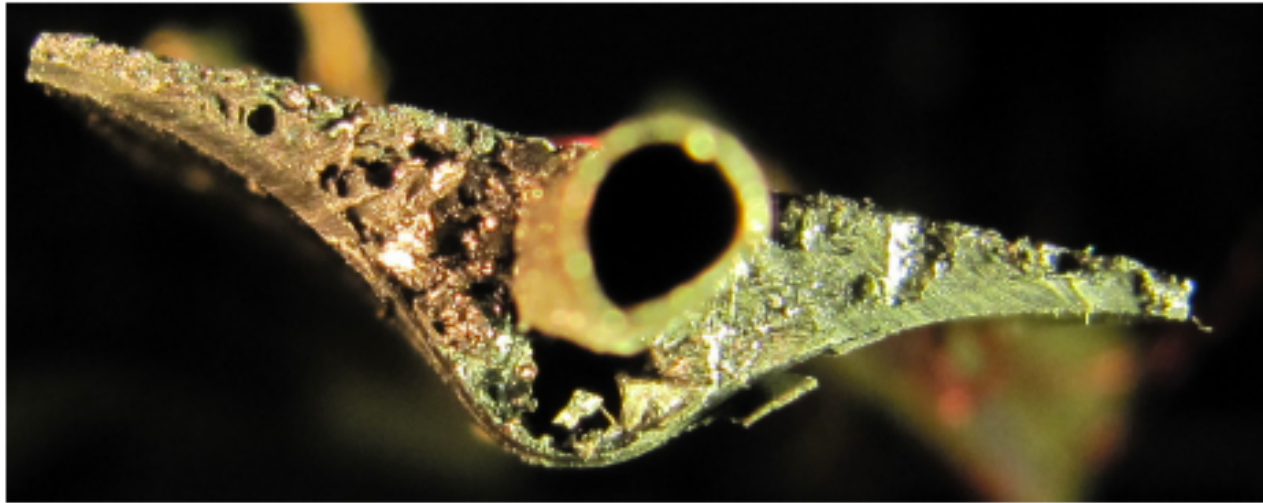
- Priority: minimize X_0
- Acceptable ΔT over sensing area: 5°C
- Dimension of sensing area: $60 \times 40 \text{ mm}$
- Heat dissipation: 2 W/cm^2 (48 W)
- Target temperature on Si detector: -10°C



Support structure outside
of acceptance region

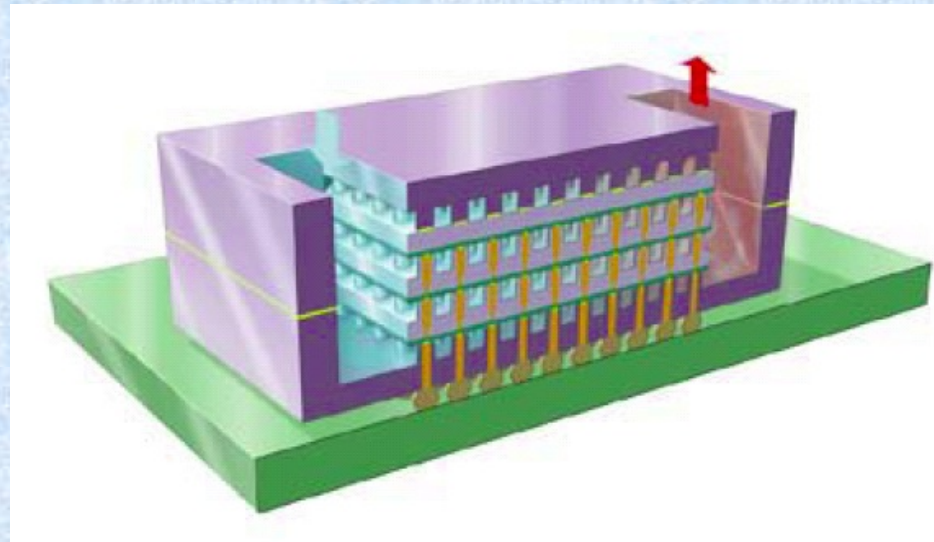
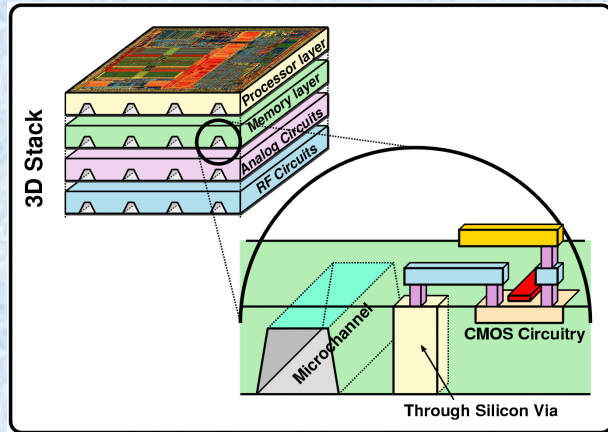
thermal interface



SLAC: Photo and diagram of IBL CO₂ prototype cooling element from Hemink thesis.**(a) Front view of Carbon Foam with 2 mm tube sticking out.****Figure 2.2:** *Front view of IBL prototype stave, with on top the sensors, supported by carbon foam and the coolant tube which is sandwiched between the Omega laminate and the carbon foam.*

CMOSAIC: 3D-IC Thermal Performance with Microscale Liquid/Evaporative Cooling

- A 3D computer chip with integrated cooling system is expected to:
 - *Overcome the limits of air cooling*
 - *Compress $\sim 10^{12}$ nanometer sized functional units (1 Tera) into one cubic centimeter: nearing the equivalent in human brain*
 - *Yield 10 to 100 fold higher connectivity*
 - *Cut energy consumption*

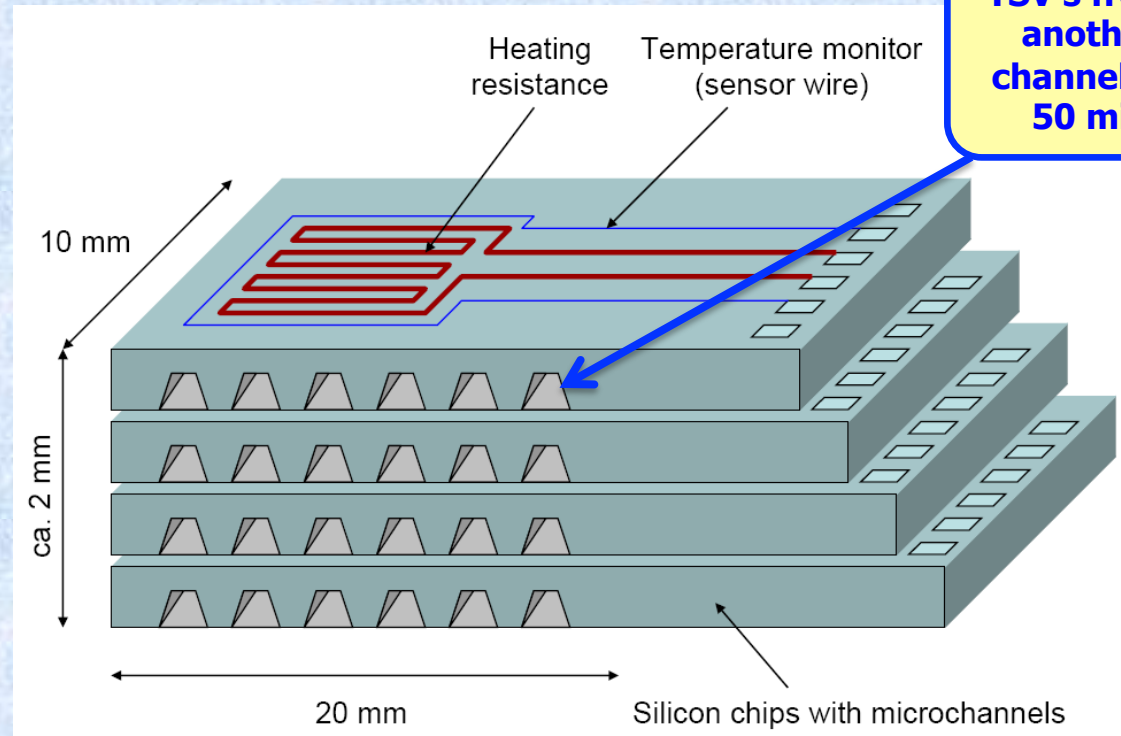


\$4million Swiss consortium lead by JR Thome (IBM, ETH, EPFL)

Laboratoire de Transfert de Chaleur et de Masse

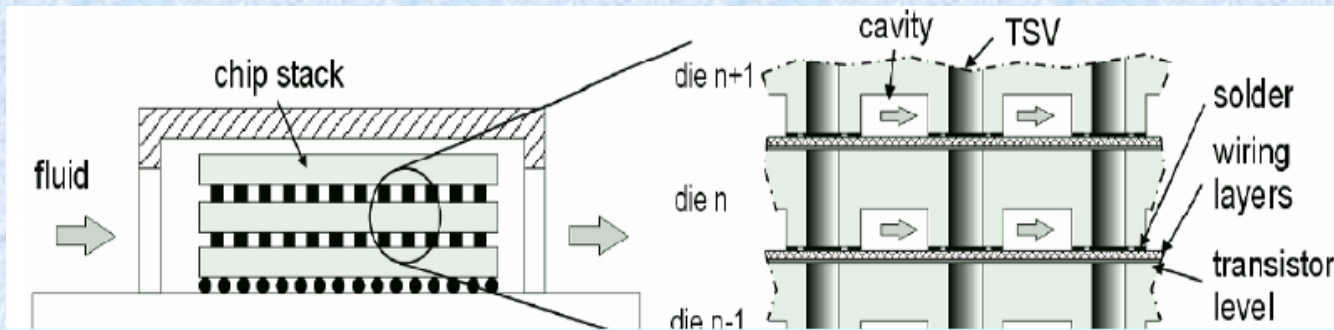
3D-IC Thermal Performance with Microscale Two-Phase Evaporative Cooling

CMOSIAC Nano-Tera Project Plan: Build, test and simulate
3D module for 3D-IC heat flow: in progress.



TSV's from one layer to another will permit channels of only about 50 microns in size!

3D-IC Thermal Performance with Microscale Two-Phase Evaporative Cooling



TSV's from
one layer to
next (10-100
per mm² with
microchannels
for 2-phase
fluid

Initial energy savings of 90% at chip level with air-cooling techniques

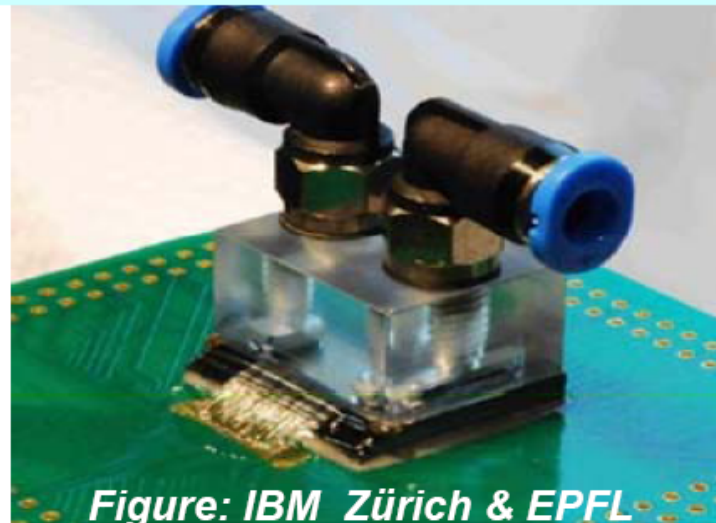
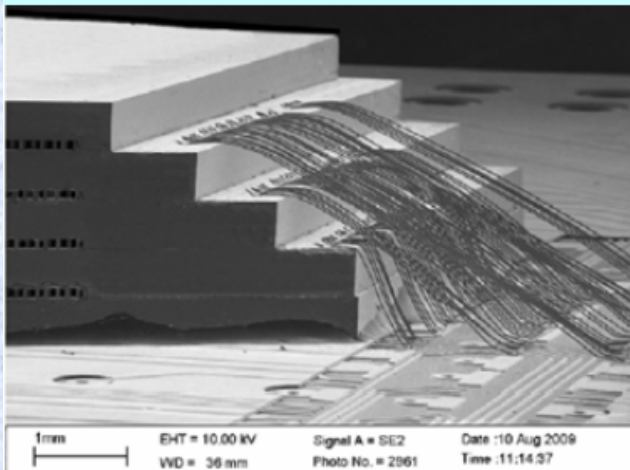
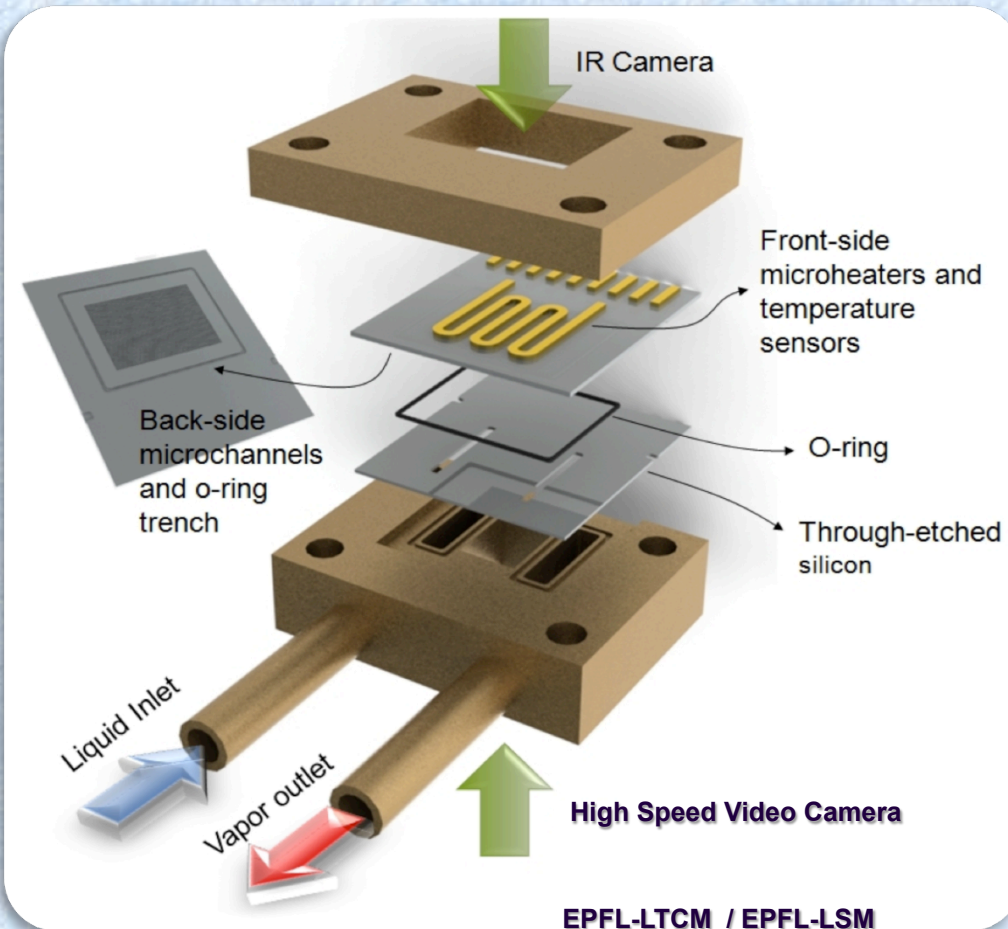


Figure: IBM Zürich & EPFL

Fabrication of 2-P Cooling Test Vehicles

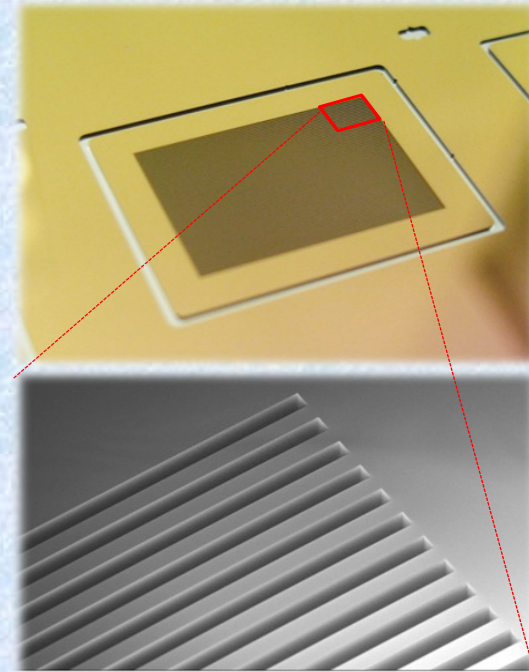
Ph.D. Student: Sylwia



EPFL-LTCM / EPFL-LSM

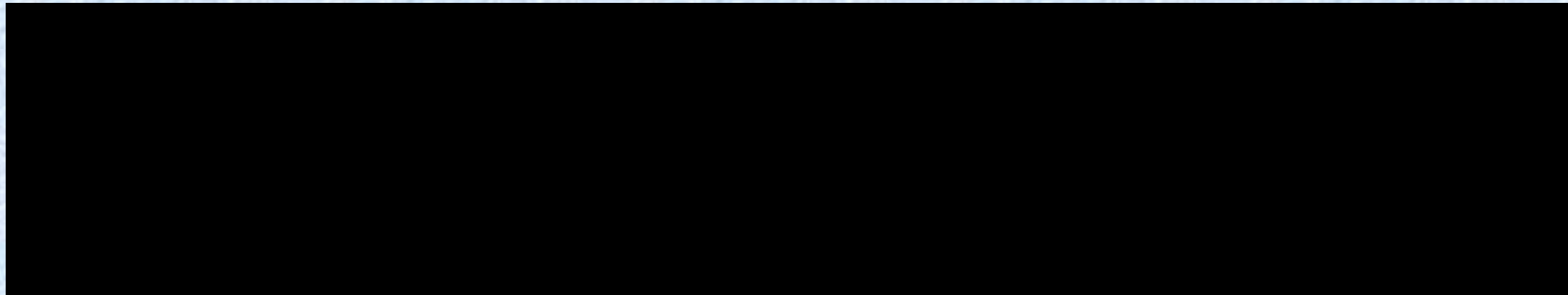
Sealed test device for two-phase micro-channel cooling experiments with front-side hotspot heaters, completely designed and manufactured at EPFL (LTCM/LSM).

Channel dimension: 50um width, 100um depth



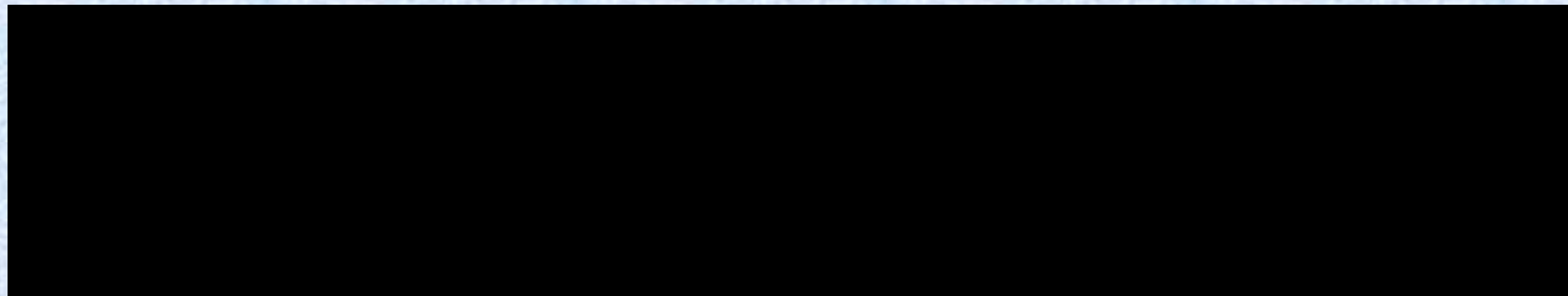
Mag = 228 X | 200µm | EHT = 3.00 kV | Signal A = InLens | Stage at T = 31.2° | EPFL-CMI

CO₂ Flow Patterns in 6 mm Horizontal Tube

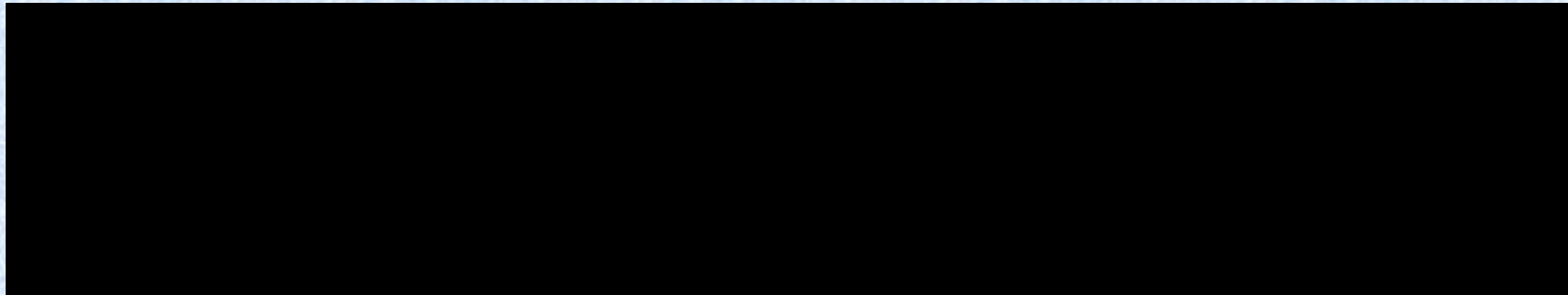


Above: Annular flow of CO₂ at 5°C, 350 kg/m²s and x=15% (Univ. Napoli II);

Below: Annular flow of CO₂ at 5°C, 500 kg/m²s and x=15% (Univ. Napoli II).

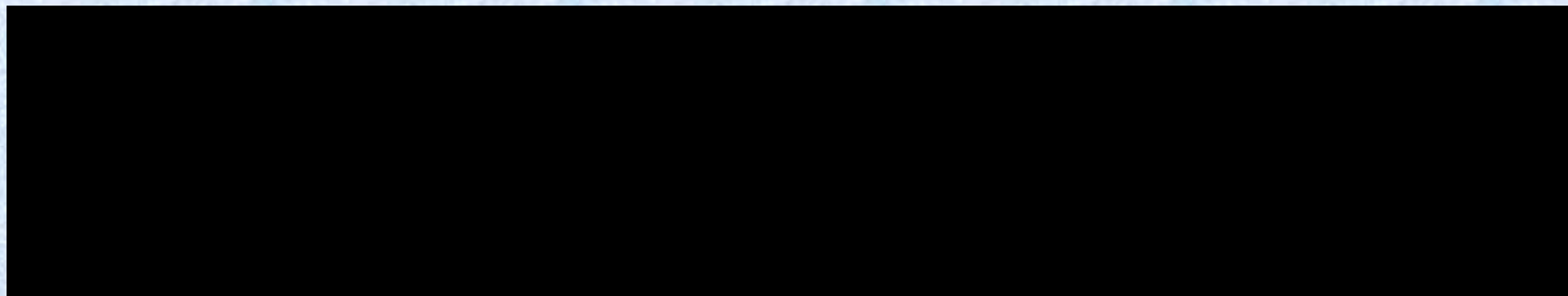


CO₂ Flow Patterns in 6 mm Horizontal Tube

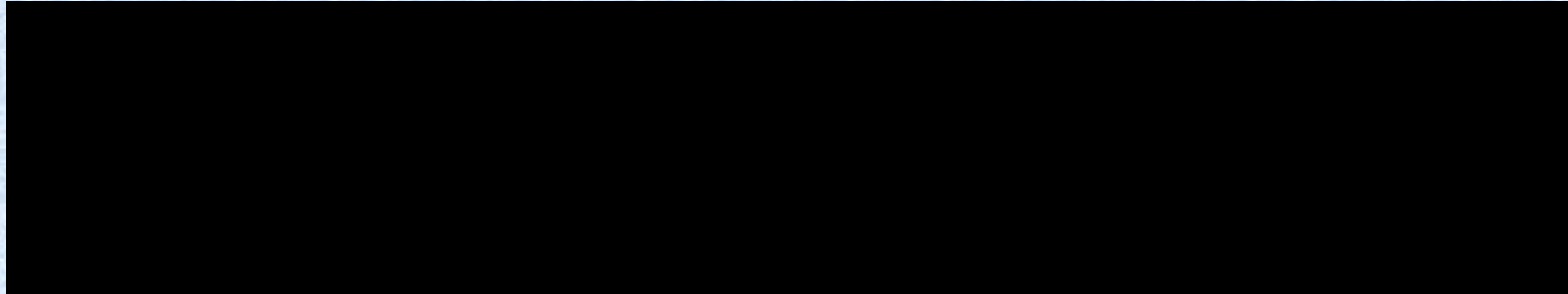


Above: Stratified-wavy flow at 5°C, 200 kg/m²s and x=75% (Univ. Napoli II);

Below: Intermittent flow at 5°C, 200 kg/m²s and x=35% (Univ. Napoli II).

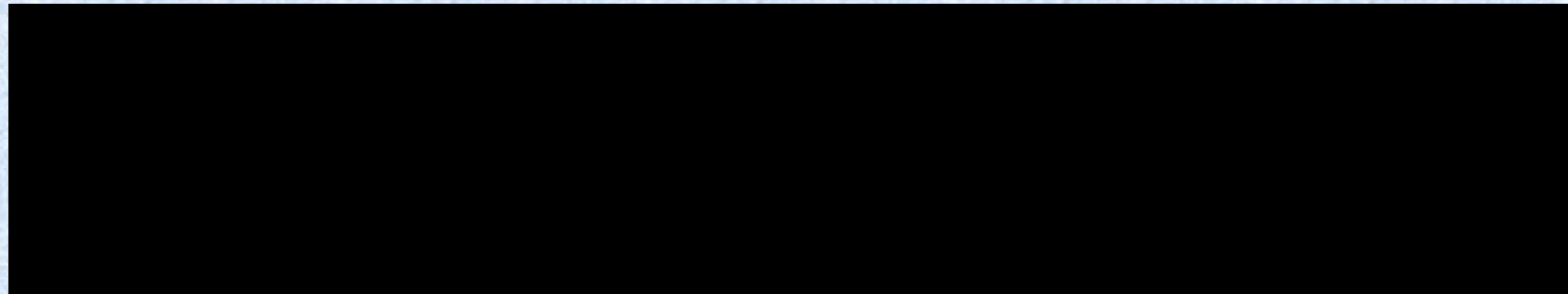


R410A Flow Patterns in 6 mm Horizontal Tube



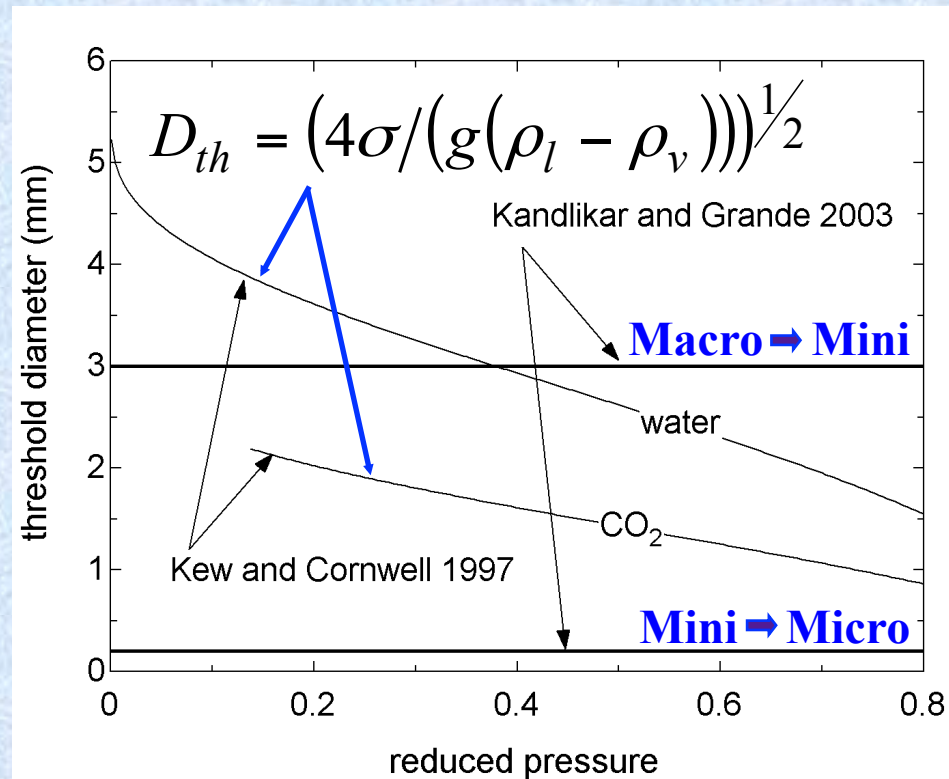
Above: Intermittent flow at 42°C, 200 kg/m²s and x=35% (Univ. Napoli II);

Below: Annular flow at 42°C, 350 kg/m²s and x=75% (Univ. Napoli II).



Where is Threshold between Macro- and Micro-Scale Two-Phase Flow for CO₂?

Kandlikar and Grande (2003) and Kew and Cornwell (1997) suggestions are shown here, the later whose Confinement Diameter D_{th} is shown for CO₂ and water.



CO₂ Flow Patterns: Ozawa et al. (IJTS)

Bubbly



Plug



Slug



Slug-annular

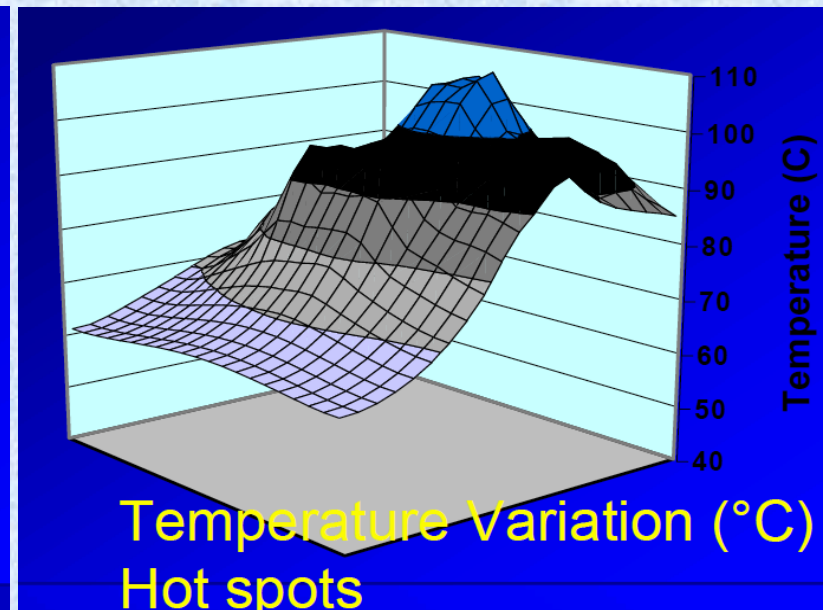
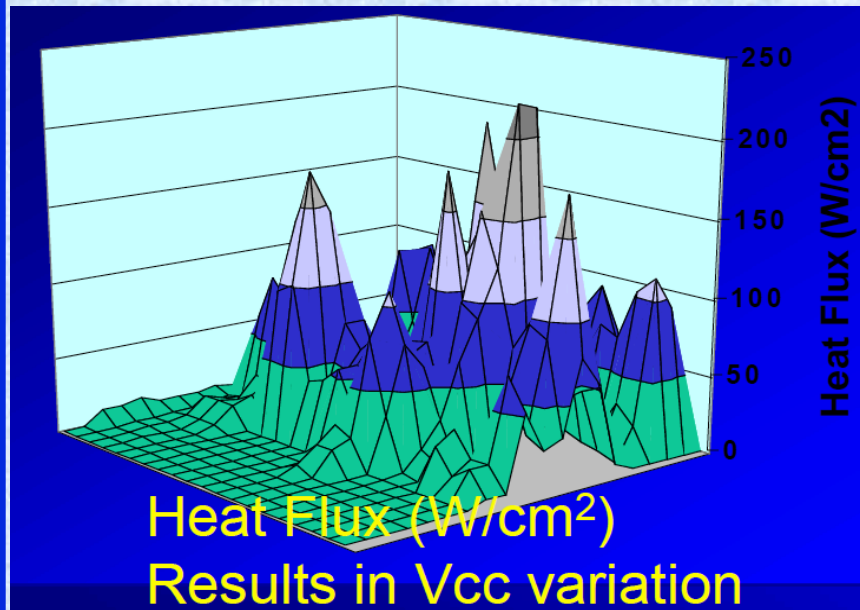


Annular



Fig. 5. Flow pattern of CO₂ ($D_p = 2.0$ mm, $p = 5.0, 6.5$ MPa, flow direction: left to right).

Example of Power Density Distribution on a Chip Hot Spots



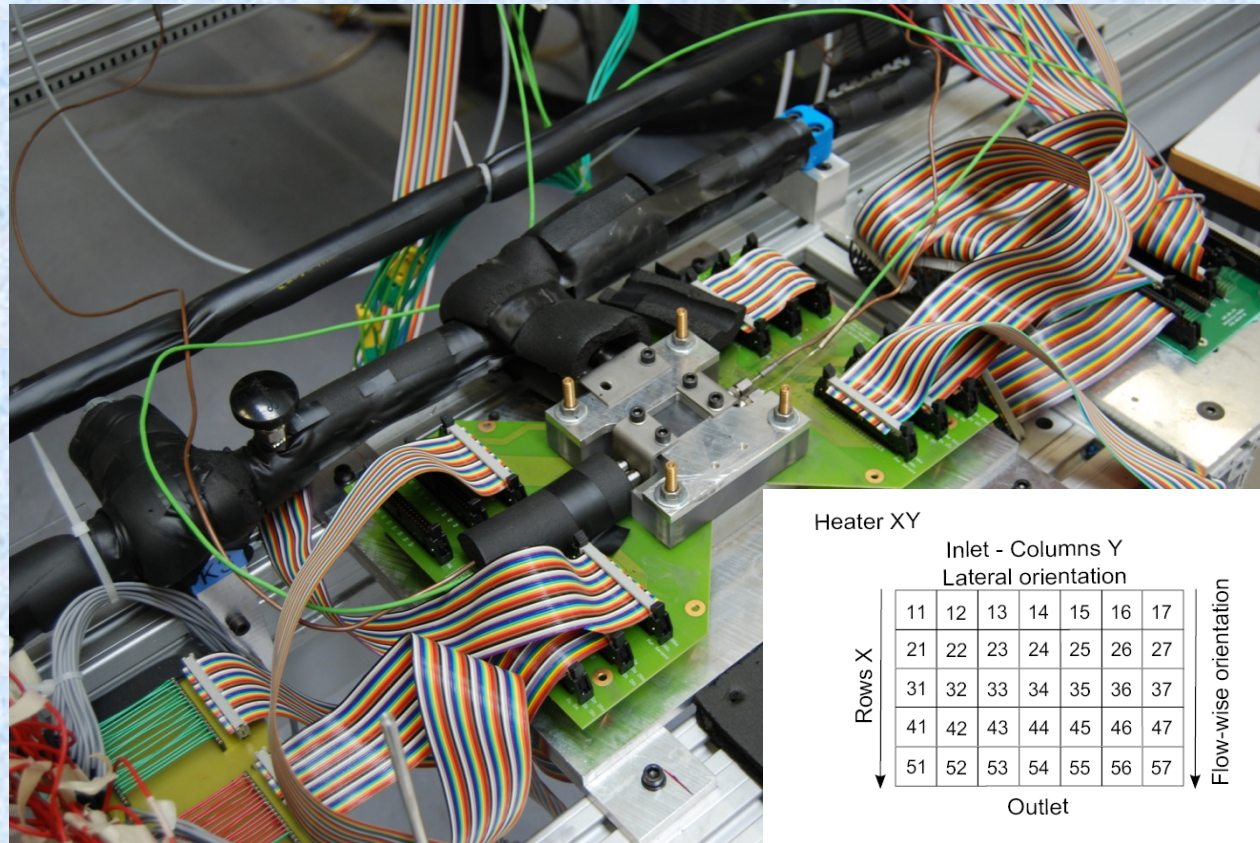
Borkar, S., 2004, Exponential Challenges, Exponential Rewards – The Future of Moore's Law, Intel report

LTCCM “35 Heater CPU” Flow Boiling Test Section

We test both liquid cooling (subcooled refrigerants) and two-phase cooling:

Hot spots up to 15 times base heat flux have been tested so far.

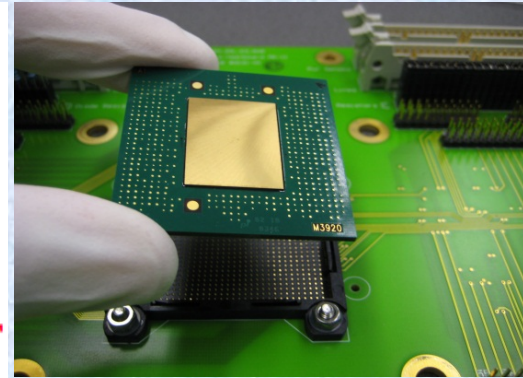
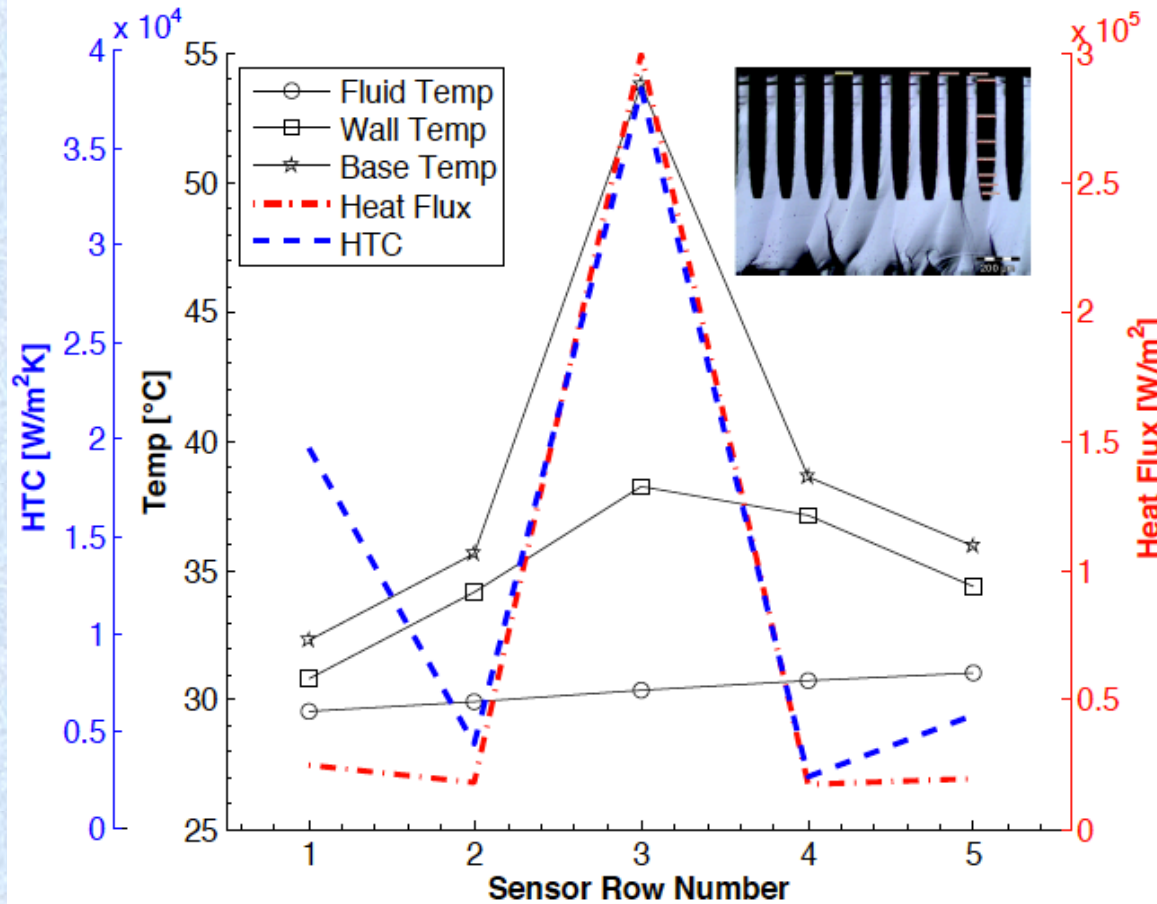
One or more hot spots can be placed anywhere in 5x7 grid.



Heater XY

		Inlet - Columns Y Lateral orientation								
Rows X	↓	11	12	13	14	15	16	17		
	21	22	23	24	25	26	27			
	31	32	33	34	35	36	37			
	41	42	43	44	45	46	47			
	51	52	53	54	55	56	57			
		Outlet								
									Flow-wise orientation	↓

Two-Phase Hot Spot Cooling: Boiling Response



Heater XY

Inlet - Columns Y
Lateral orientation

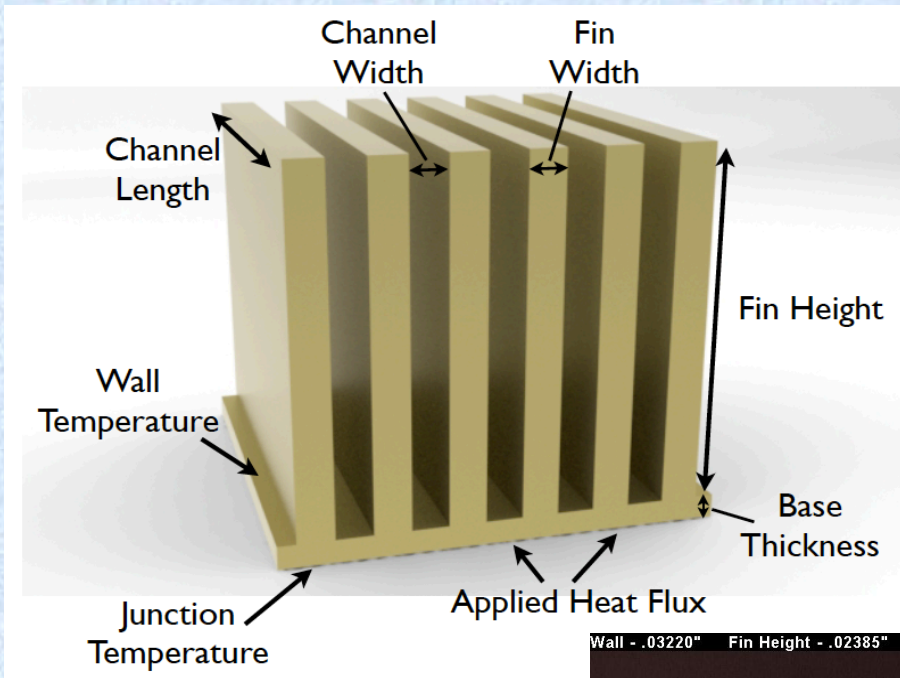
	11	12	13	14	15	16	17	
	21	22	23	24	25	26	27	
	31	32	33	34	35	36	37	
	41	42	43	44	45	46	47	
	51	52	53	54	55	56	57	
	Outlet							

Rows X (vertical axis), Flow-wise orientation (vertical axis)

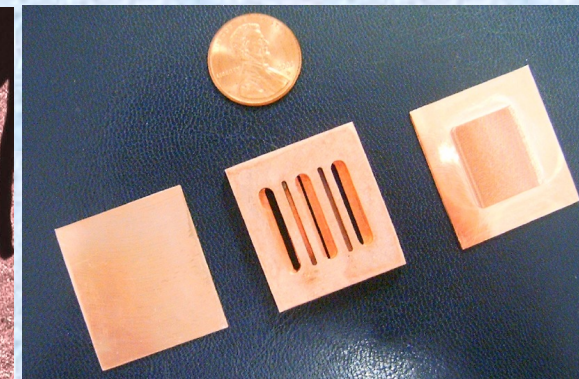
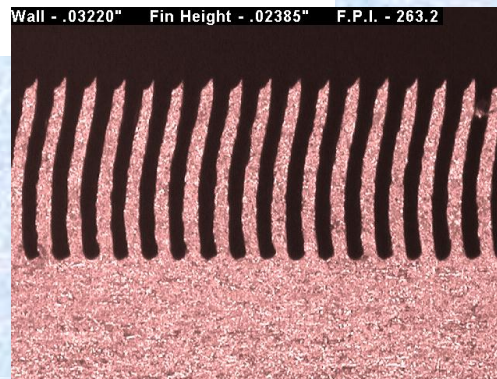
Hot spot heat flux is 15 times higher, htc is 8 times higher so wall superheat is only 2 times higher!

Thermal profile of pseudo-chip with 35 local heaters and 35 local temperature sensors, being cooled by a two-phase refrigerant evaporating in 135 parallel microchannels of 87 micron width engraved in opposite face of the silicon die (*Costa-Patry et al of LTCM at THERMINIC 2010 Barcelona*).

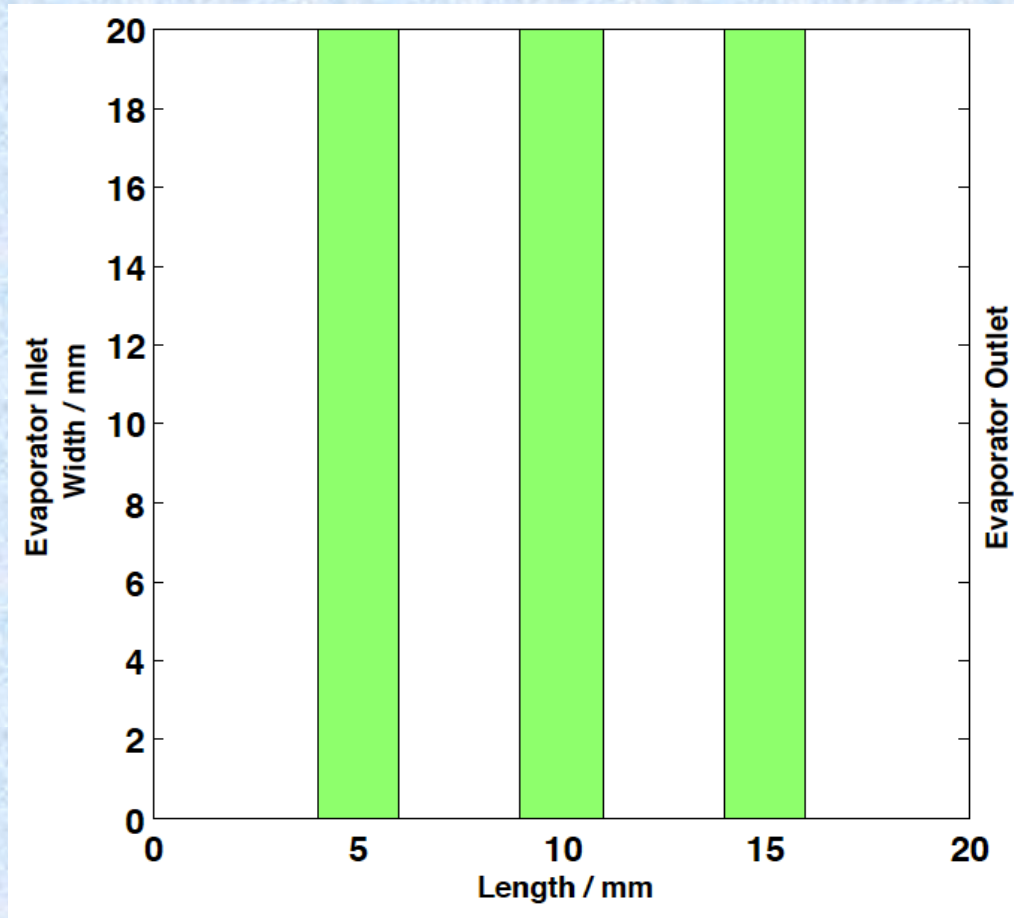
Two-Phase Hot Spot Simulations: LTCM Code



- Footprint 19.3 mm x 13.2 mm (Intel Xeon 5500)
- 60°C saturation temperature
- Fin height : 1.7mm
- Fin width : 170µm
- Channel width : 170µm

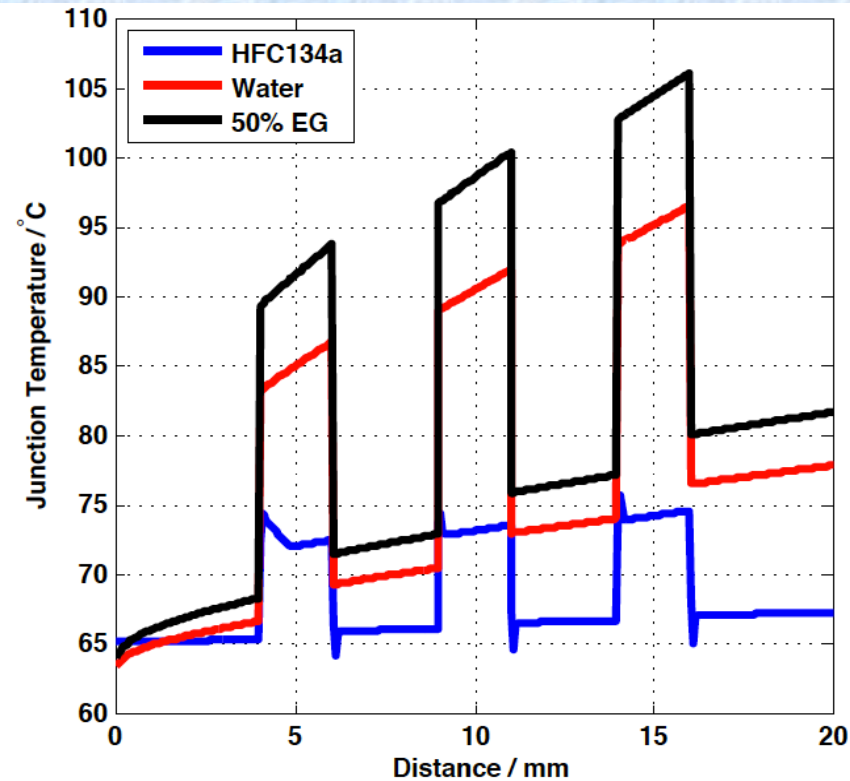
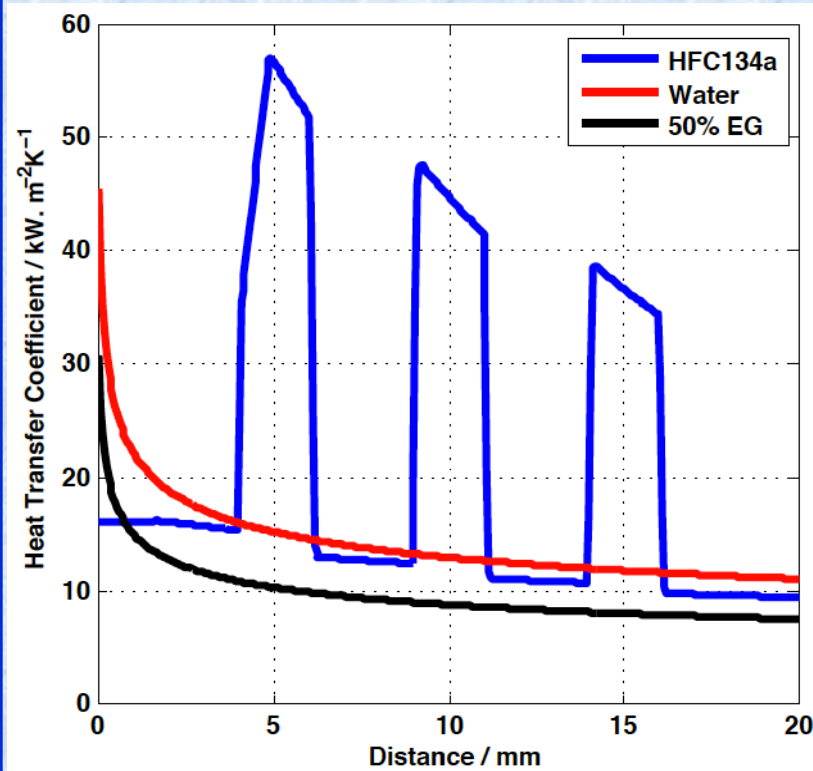


Hot Spot Cooling Simulations

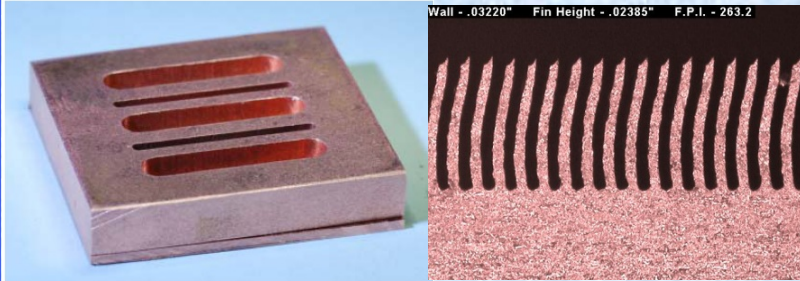


Base heat flux:
 50 W/cm^2
Hotspot heat flux:
 200 W/cm^2

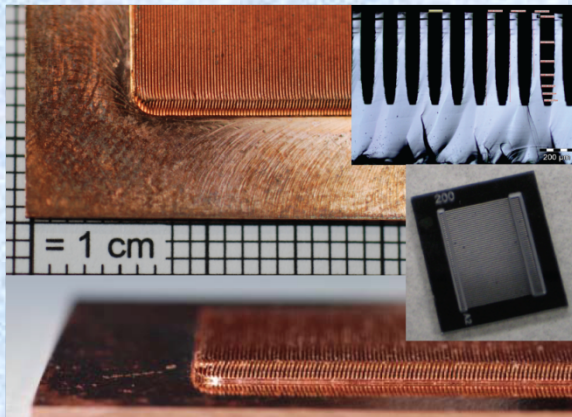
Heat Transfer Coefficient & Junction Temperature



Two-Phase On-Chip Cooling of Blade Server



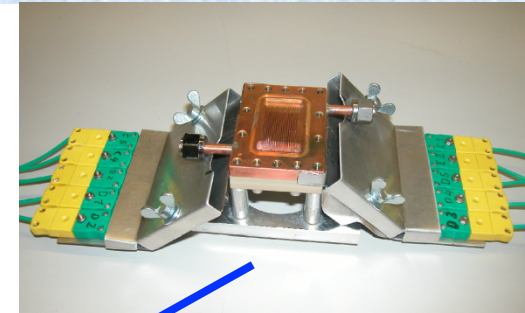
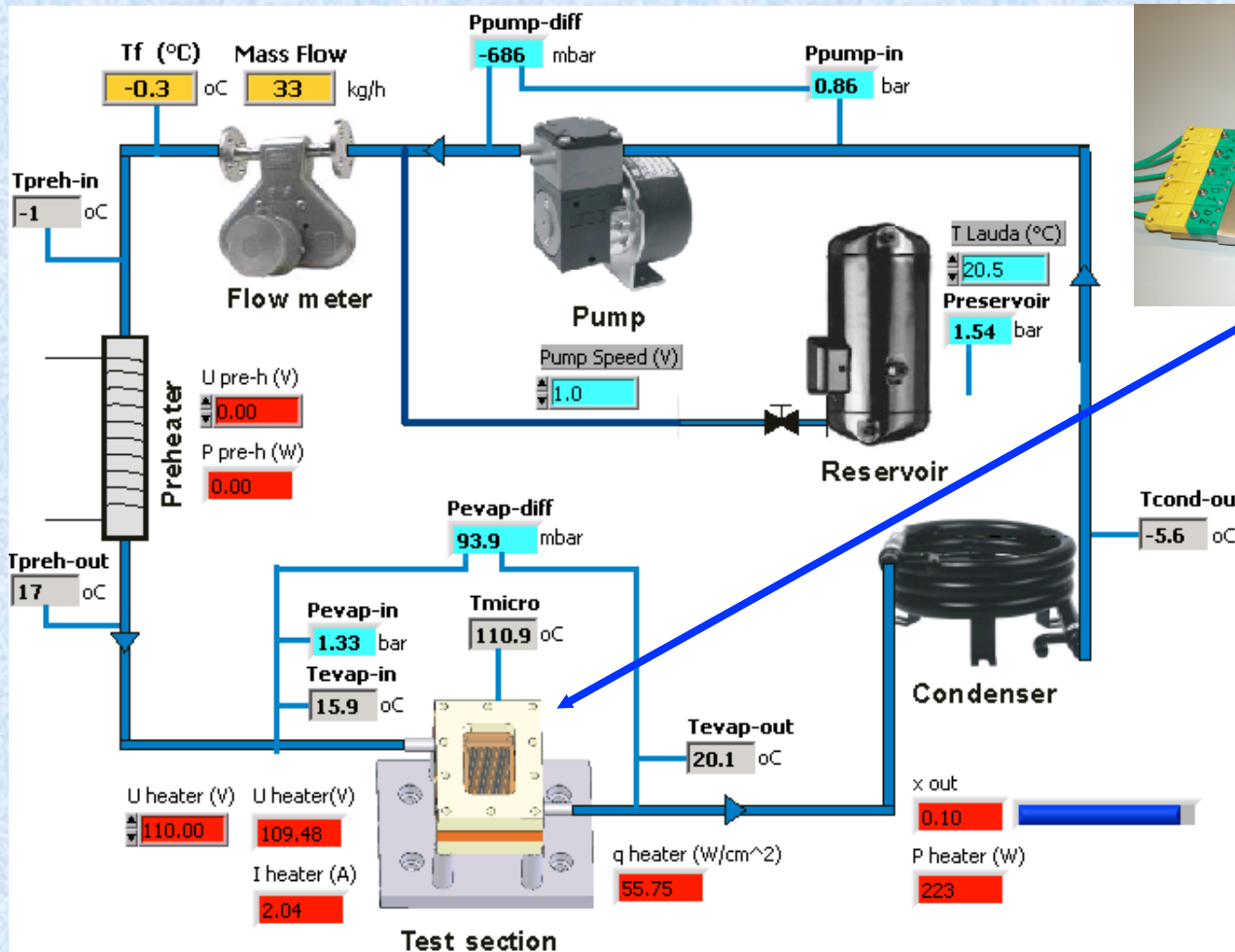
- 60% or more improvement in energy efficiency
- Heat can be recovered
 - Reused elsewhere
 - Reduce CO₂ footprint
- Can operate at higher temperatures and still be cooled efficiently



Water-Cooled IBM BladeCenter HS22

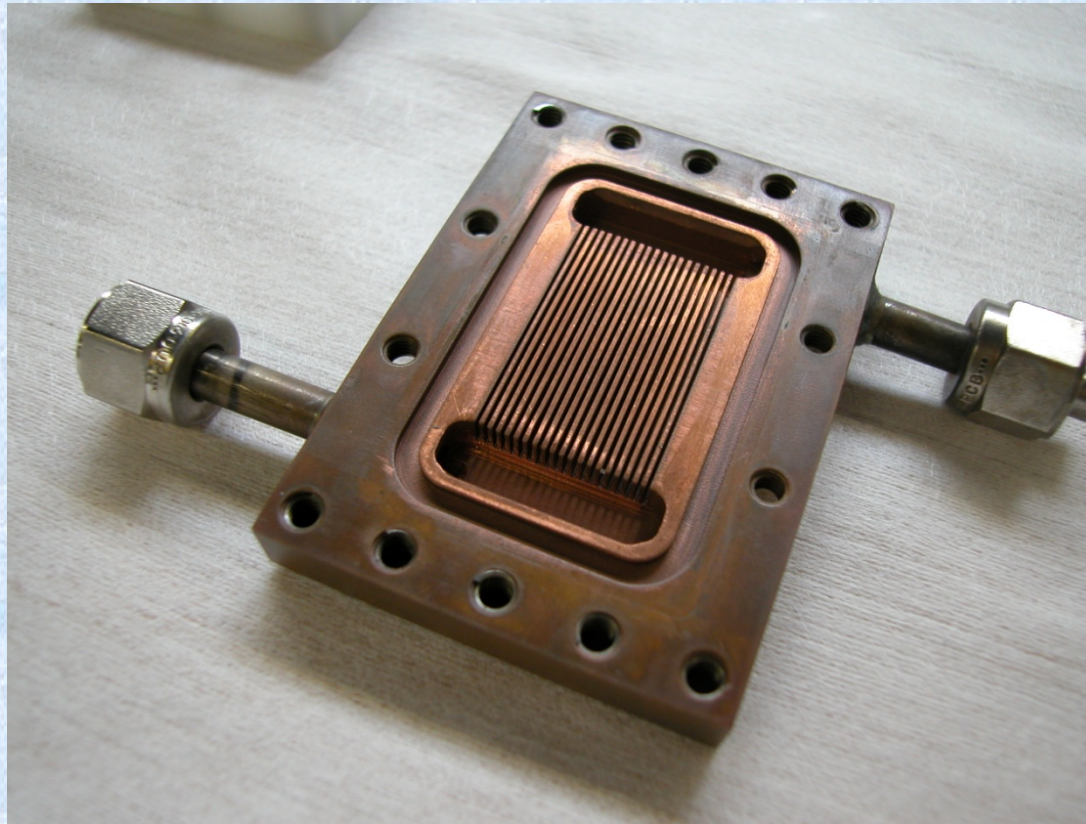
Credit: IBM Research – Zurich

CPU Multi-Microchannel Flow Boiling Test Facility



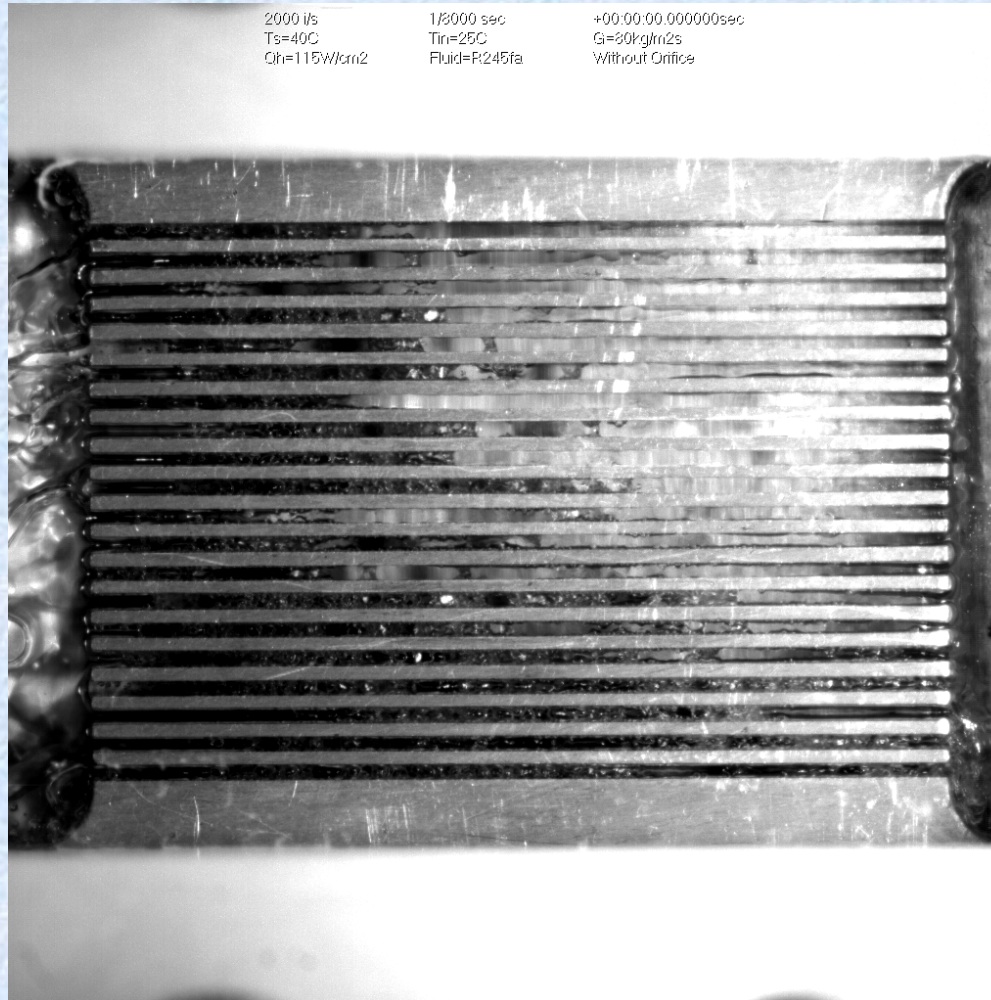
Flow loop for copper micro-channel array: currently used to measure CHF for R-134a, R-245fa and R-236fa with flow visualization using high speed camera. Diagram of Park (LTCM).

CPU Microchannel Flow Boiling Cooling at LTCM



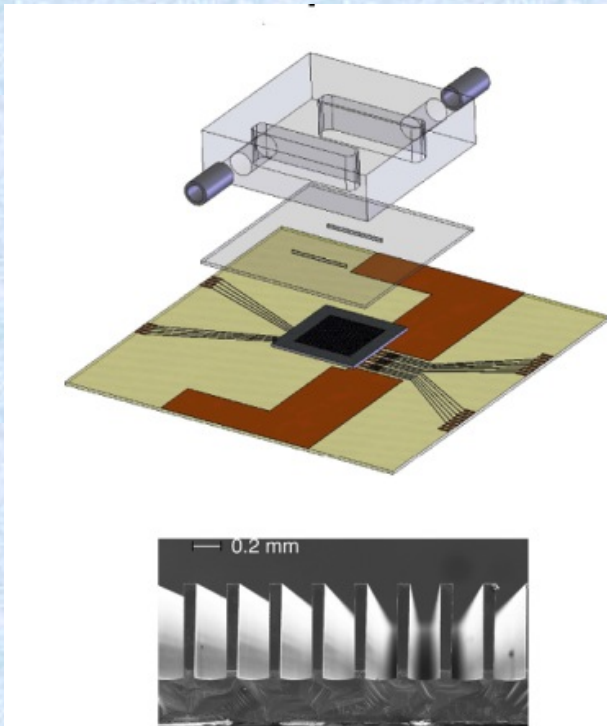
Multi-microchannel evaporator in copper fabricated at LTCM: 20 channels (0.45 x 4.0 mm) and dissipates 340 W/cm^2 with a low pressure refrigerant as coolant (*LTCM PhD thesis of J.E. Park (2008)*).

Video at High Heat Flux in Copper: Poor Flow Distribution

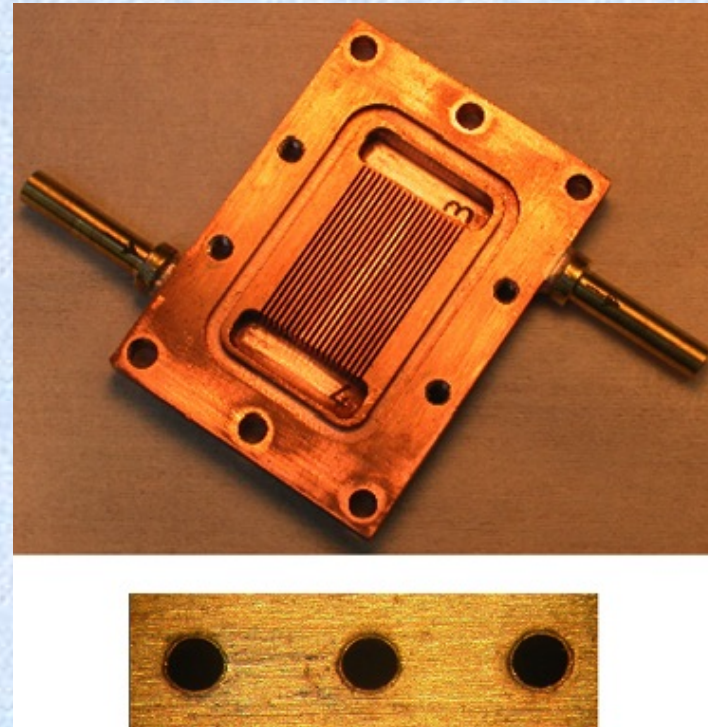


Maximum heat flux dissipation possible is only about 115 W/cm^2 (as a result of mal-distribution and back flow, there is over heating in liquid starved/ dry area!). Video of LTCM.

Micro-Evaporators: Basic Geometry and Flow Stabilization



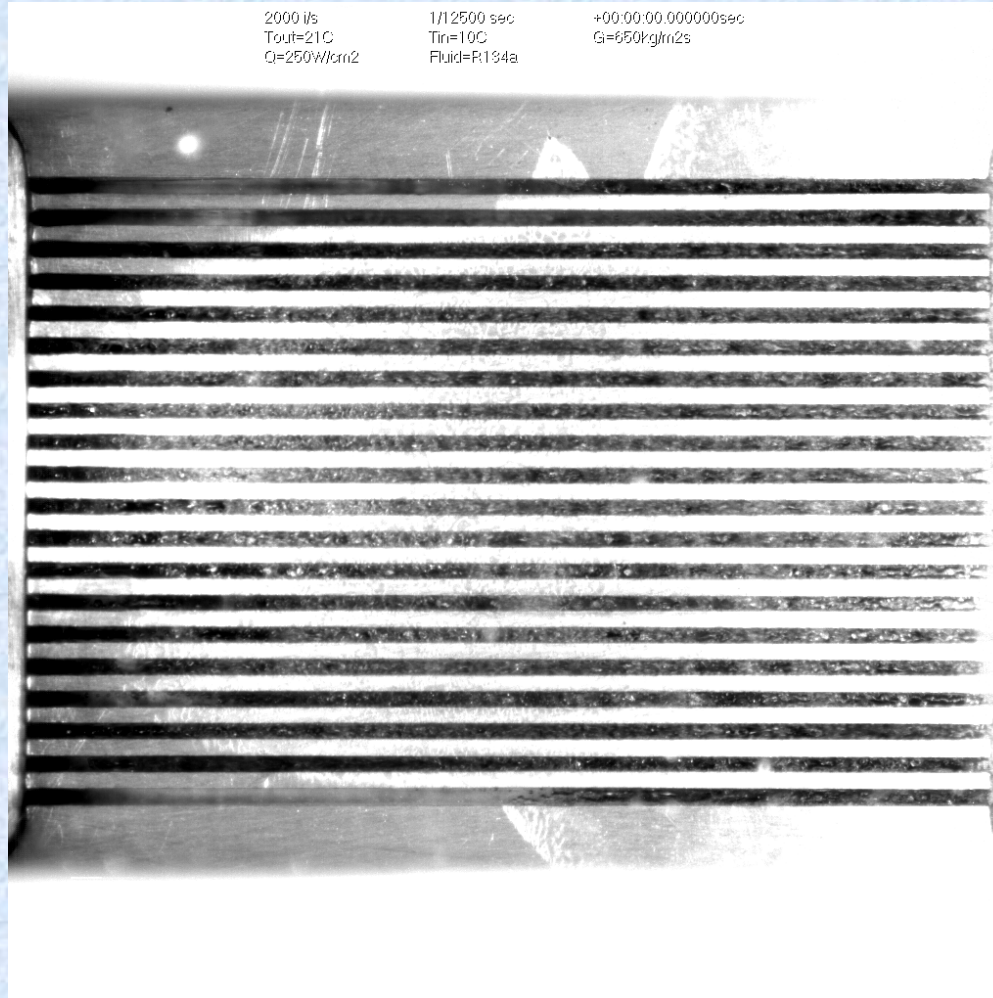
(a)



(b)

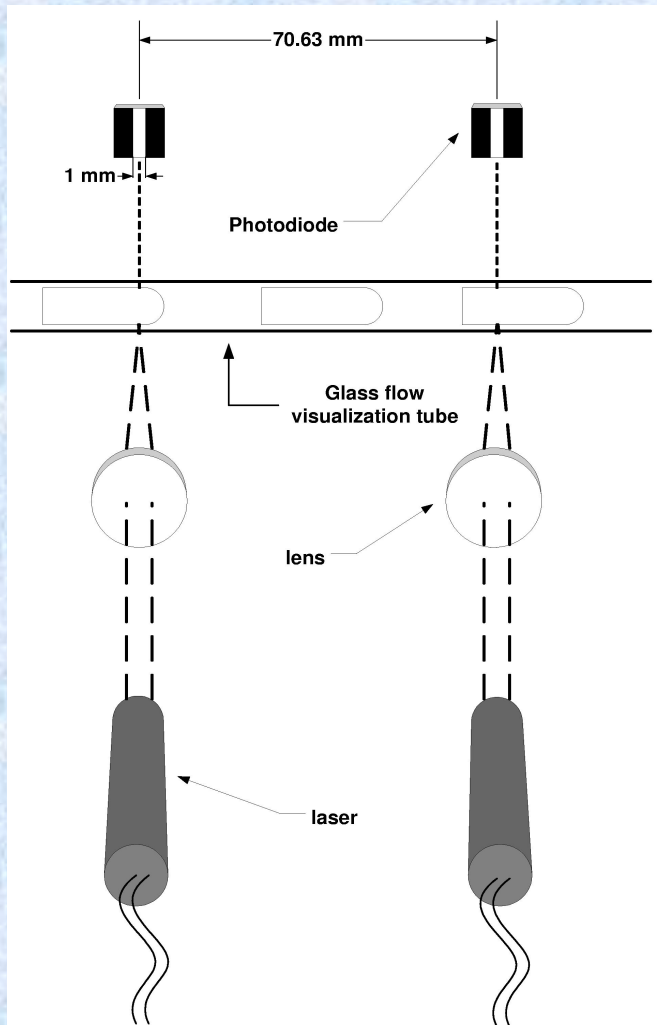
Examples of (a) silicon micro-evaporator with micro-channels etched on the chip silicon die and (b) copper micro-evaporator test section made by electro-erosion with an inlet orifice insert.

Video at High Heat Flux in Copper: Good Flow Distribution

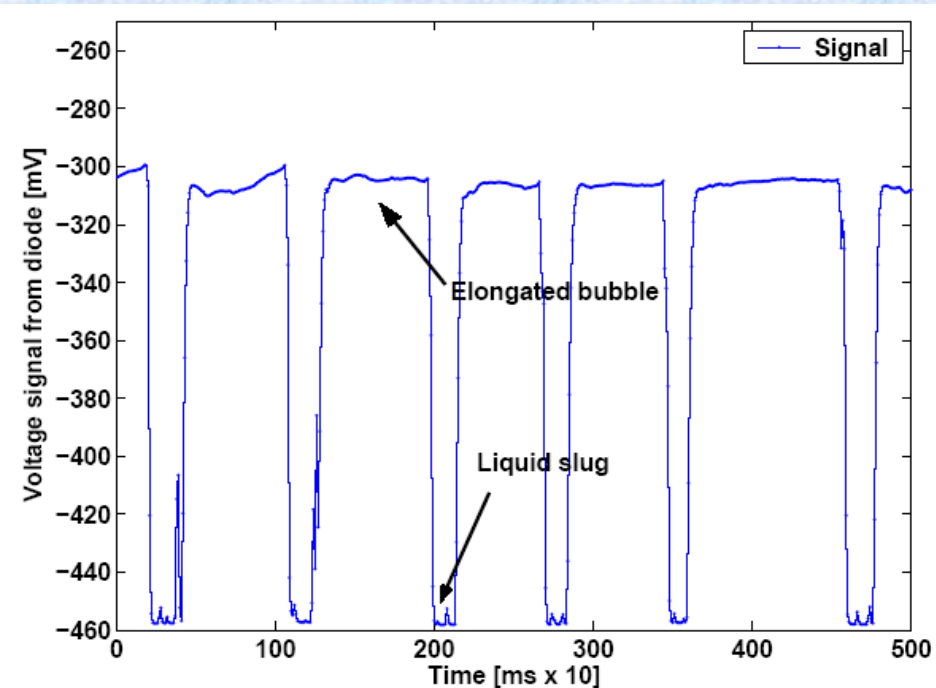


Maximum heat flux dissipation possible is at least 340 W/cm^2 using inlet flow restrictions to prevent back flow and create uniform flow distribution (shown here at 250 W/cm^2 at 2000 images/sec). Video of LTCM.

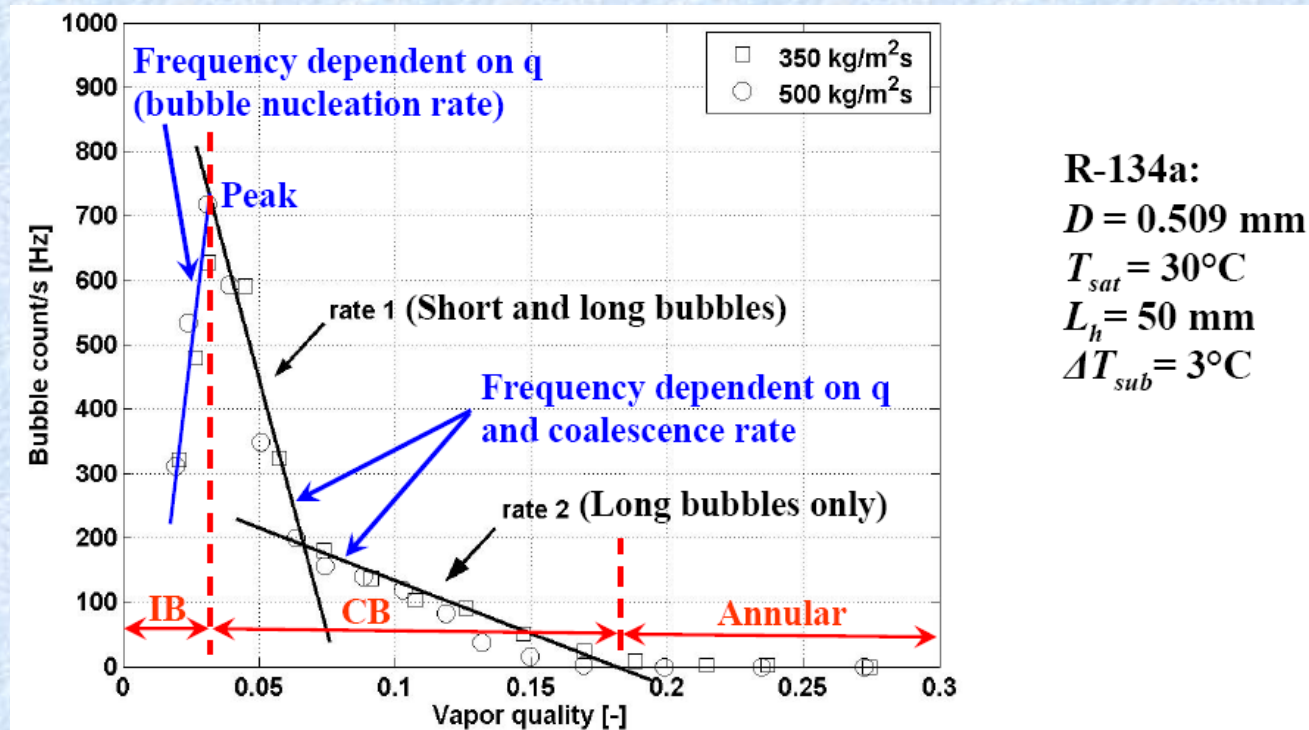
LTCM Optical Measurement Technique for 2-Phase Flow



- It yields:
- Bubble velocity
 - Void fraction
 - Bubble length
 - Bubble frequency
 - Flow pattern

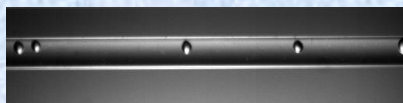


Flow Patterns/Bubble Frequencies in Micro-Channels

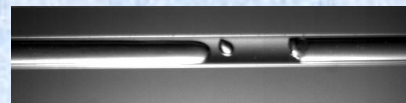


R-134a:
 $D = 0.509$ mm
 $T_{sat} = 30^\circ\text{C}$
 $L_h = 50$ mm
 $\Delta T_{sub} = 3^\circ\text{C}$

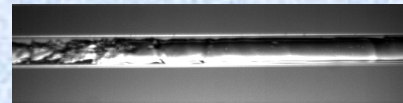
*Revellin,
 Thome et al.,
 Int. J.
 Multiphase
 Flow, Vol.
 32, pp.
 755-774,
 2006.
 Awarded
 Eurotherm
 PhD thesis
 prize.*



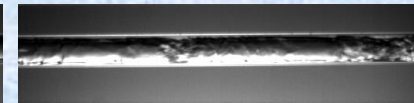
bubbly



slug

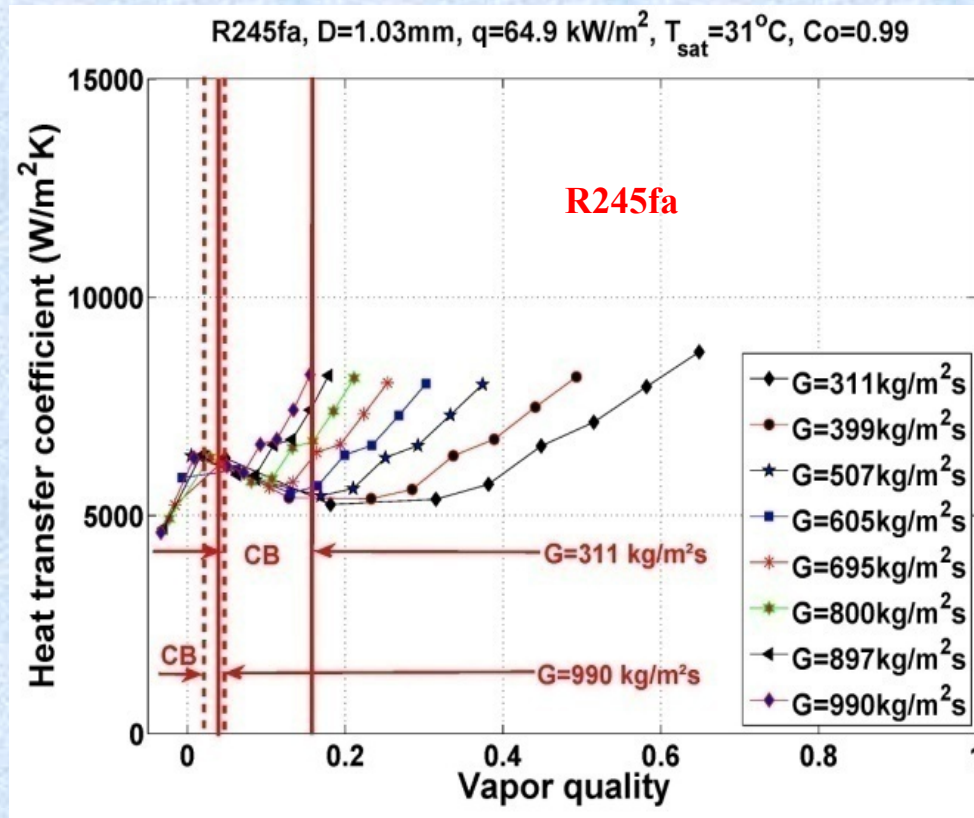


churn – semi-annular



annular

Flow Boiling Heat Transfer: Flow Pattern Effects (Ong)



1. IB/CB flow regime nearly disappears at high mass velocities while the annular flow becomes nearly totally dominant.
2. Heat transfer coefficient rises in the sub-cooled region to the IB region (ONB).
3. Decreasing trend in htc in the CB flow but rising in the annular flow regime.

Flow Boiling HT in CB Zone

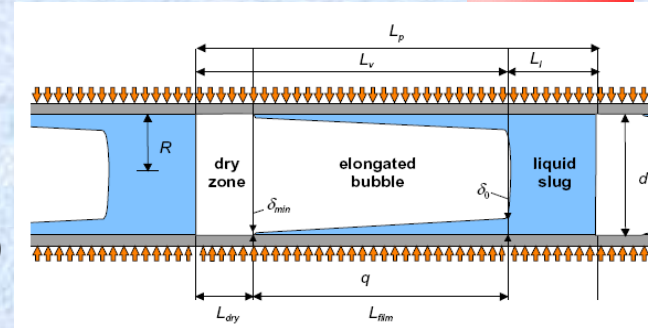
Three zone model of Thome et al. (2004) →

$$h(z) = \frac{t_{liquid}}{\tau} h_{liquid}(z) + \frac{t_{film}}{\tau} h_{film}(z) + \frac{t_{dry}}{\tau} h_{vapor}(z)$$

$$f_{opt} = \left(\frac{q}{q_{ref}}\right)^{n_f}$$

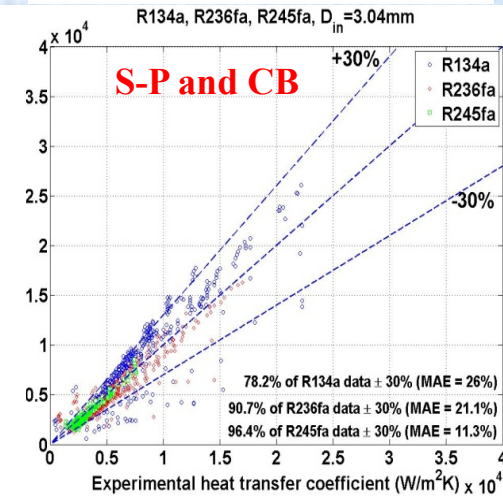
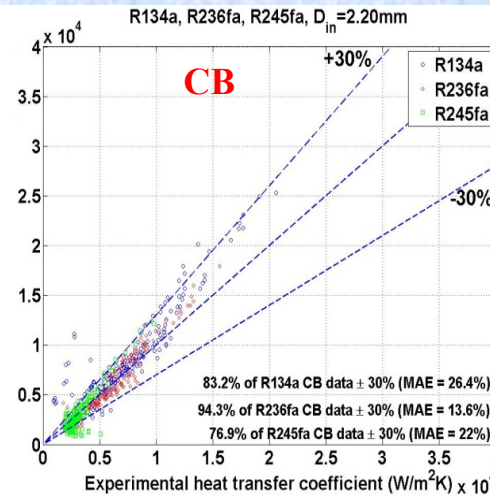
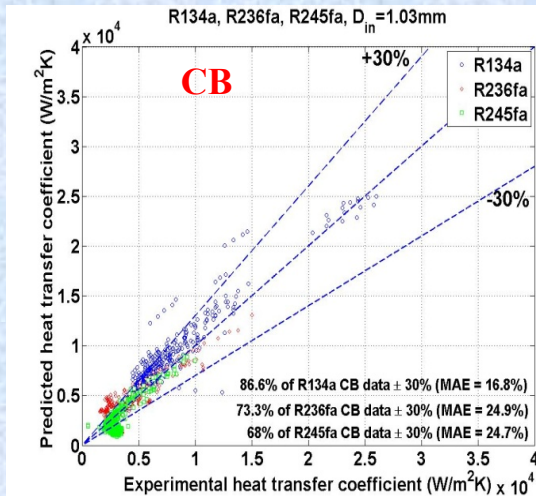
$$n_f = 1.74, \delta_{min} = 300nm, C_{\delta 0} = 0.29$$

Replacing δ_{min} with actual roughness gives better results



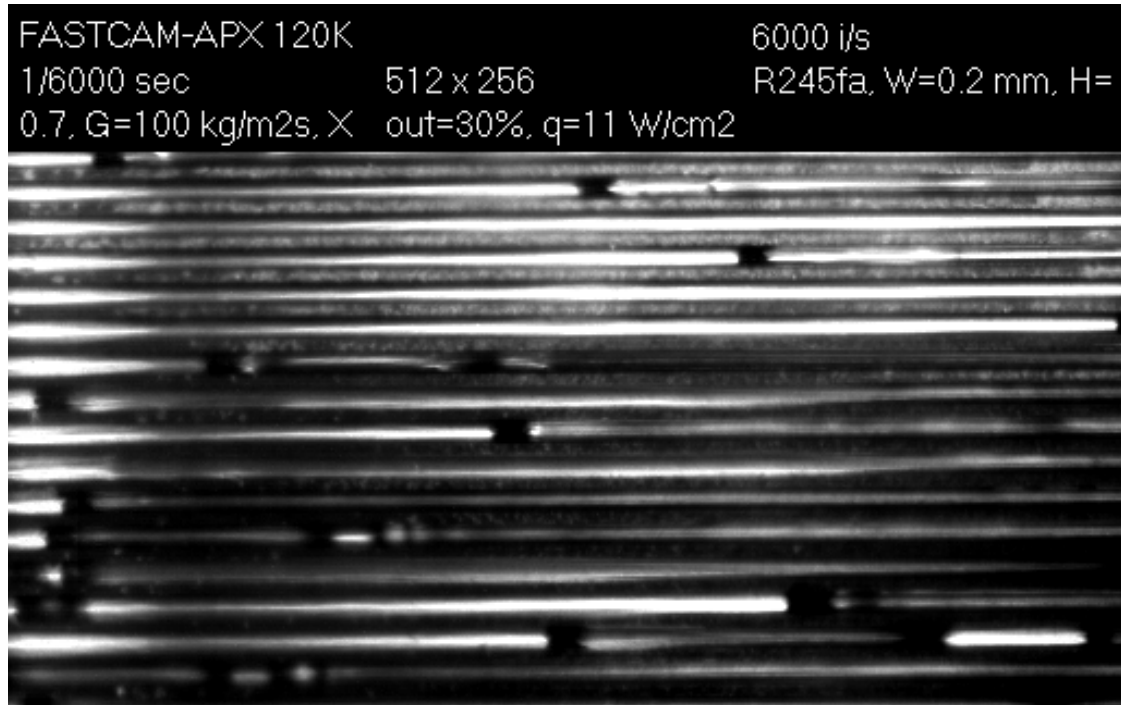
Surface roughness

D_{int} (mm)	δ_{min} (nm)
1.03	595.85
2.20	826.99
3.04	796.81



New: importance of surface roughness now found in 3 different LTCM studies!
Laboratoire de Transfert de Chaleur et de Masse

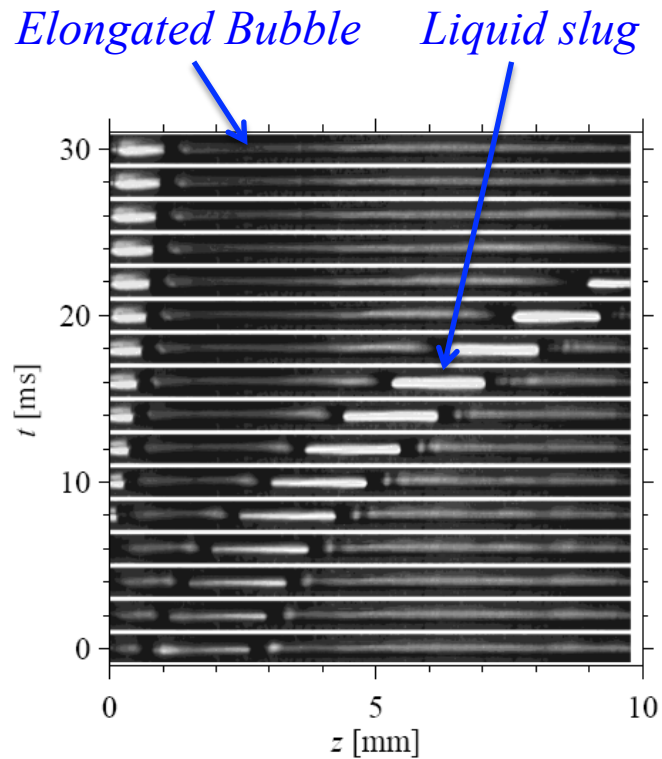
New Time Strip Analysis of Two-Phase Flow



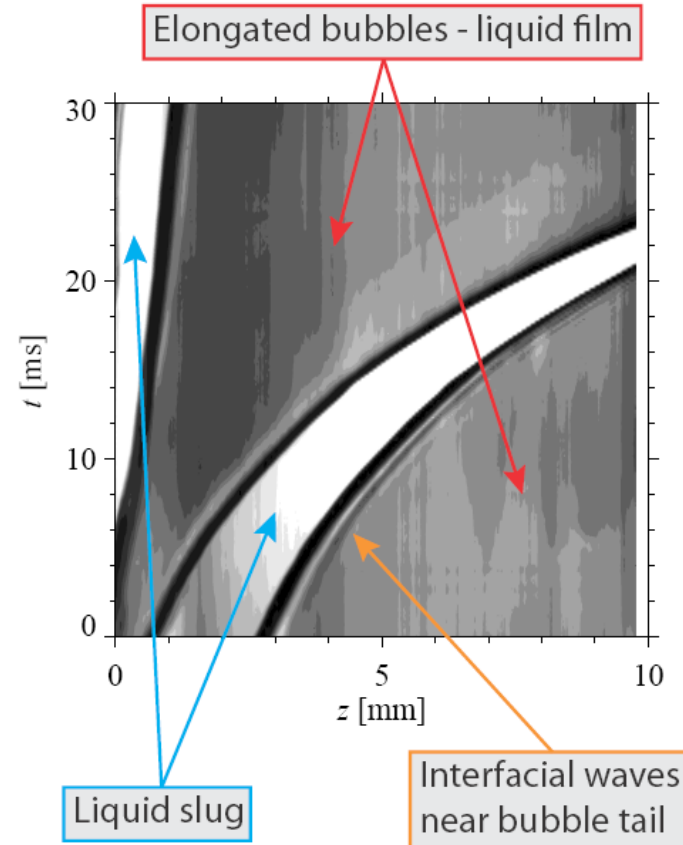
- Photron Fastcam-APX120K CMOS camera at 6 kHz and a frame size of 512×256 pixels.
- Resolution of 1 pixel per $19 \mu\text{m}$, resulting in a captured area of size $9.8 \times 6.2 \text{ mm}$ just downstream of the inlet plenum.

New Time Strip Analysis of Two-Phase Flow

Channel frame sequence

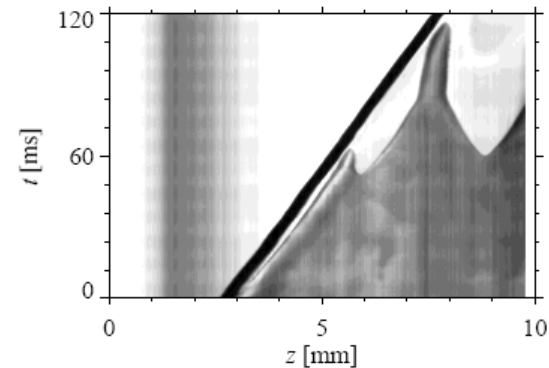
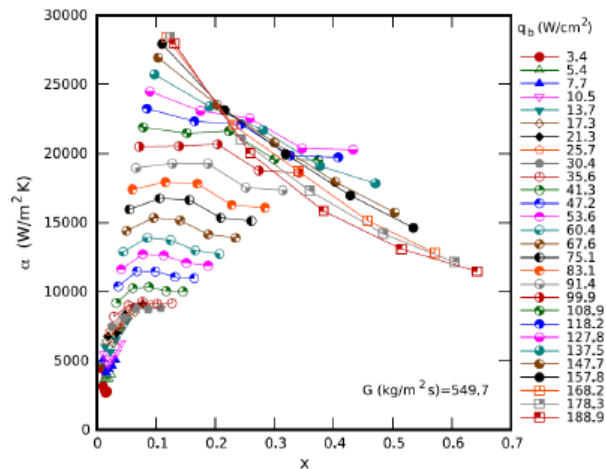
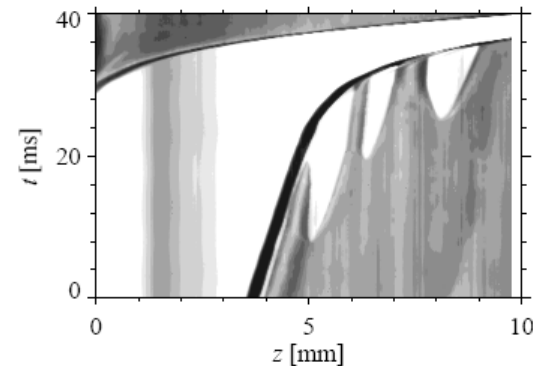
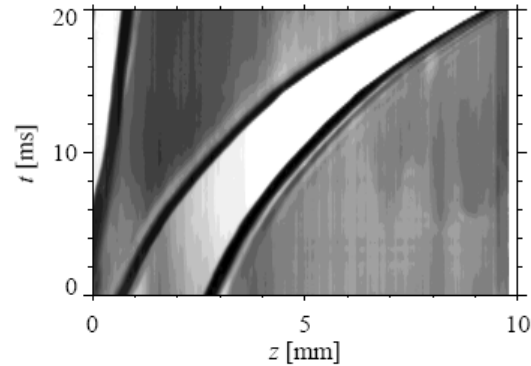


Channel time strip



Borhani-Agostini-Thome
in *IJHMT* 2010

New Time Strip Analysis of Two-Phase Flow



- Intermittent dewetting-dryout-rewetting affects the gradient of the heat transfer coefficient - vapour quality trend.

Simulations of Cheng-Thome Heat Transfer Model and Map for CO₂

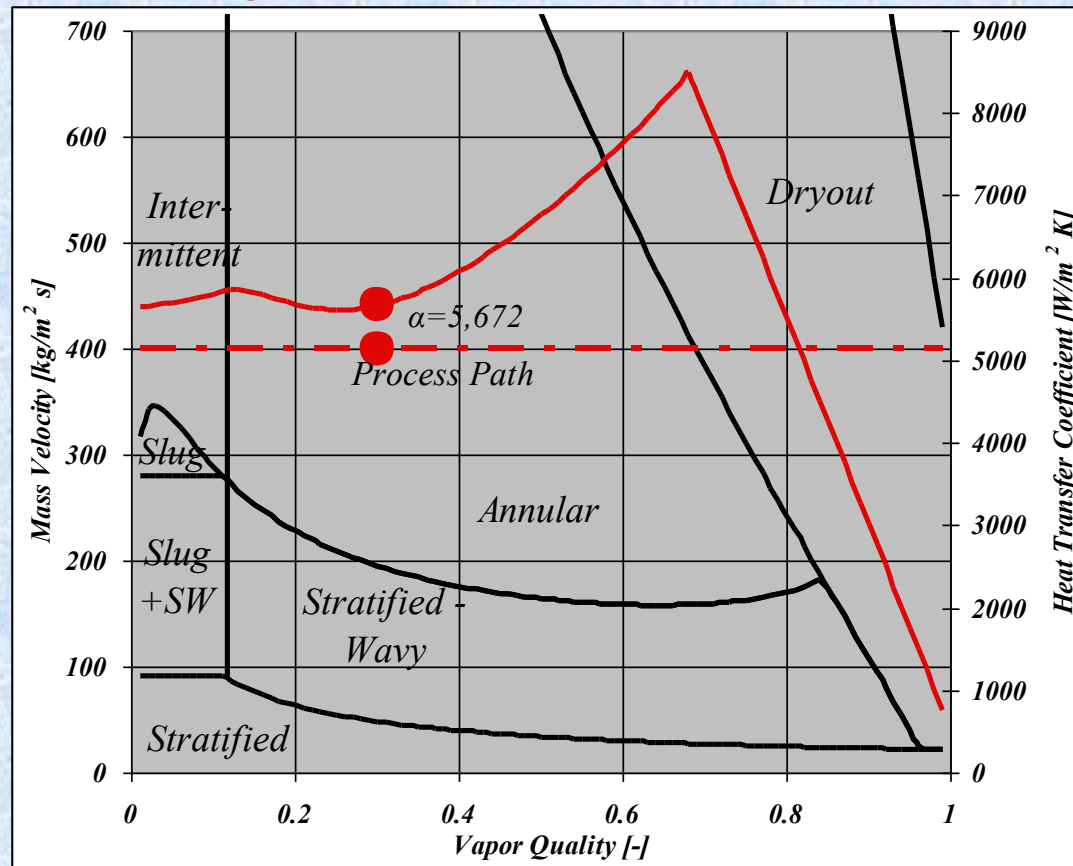


Figure 6. Simulation for 7 mm channel at following conditions: $q = 10$ kW/m², T_{sat} at -20°C and $G = 400$ kg/m²s with indicated value at $x = 0.30$.

Simulations of Cheng-Thome Heat Transfer Model and Map for CO₂

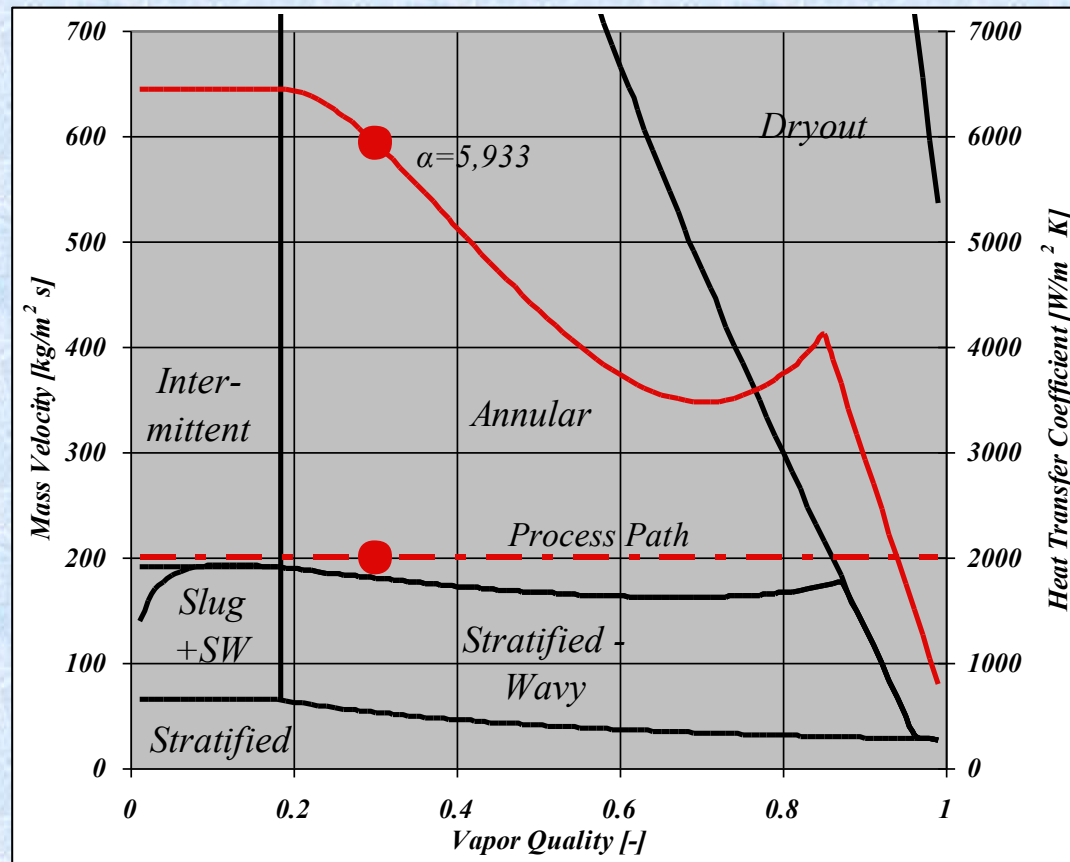
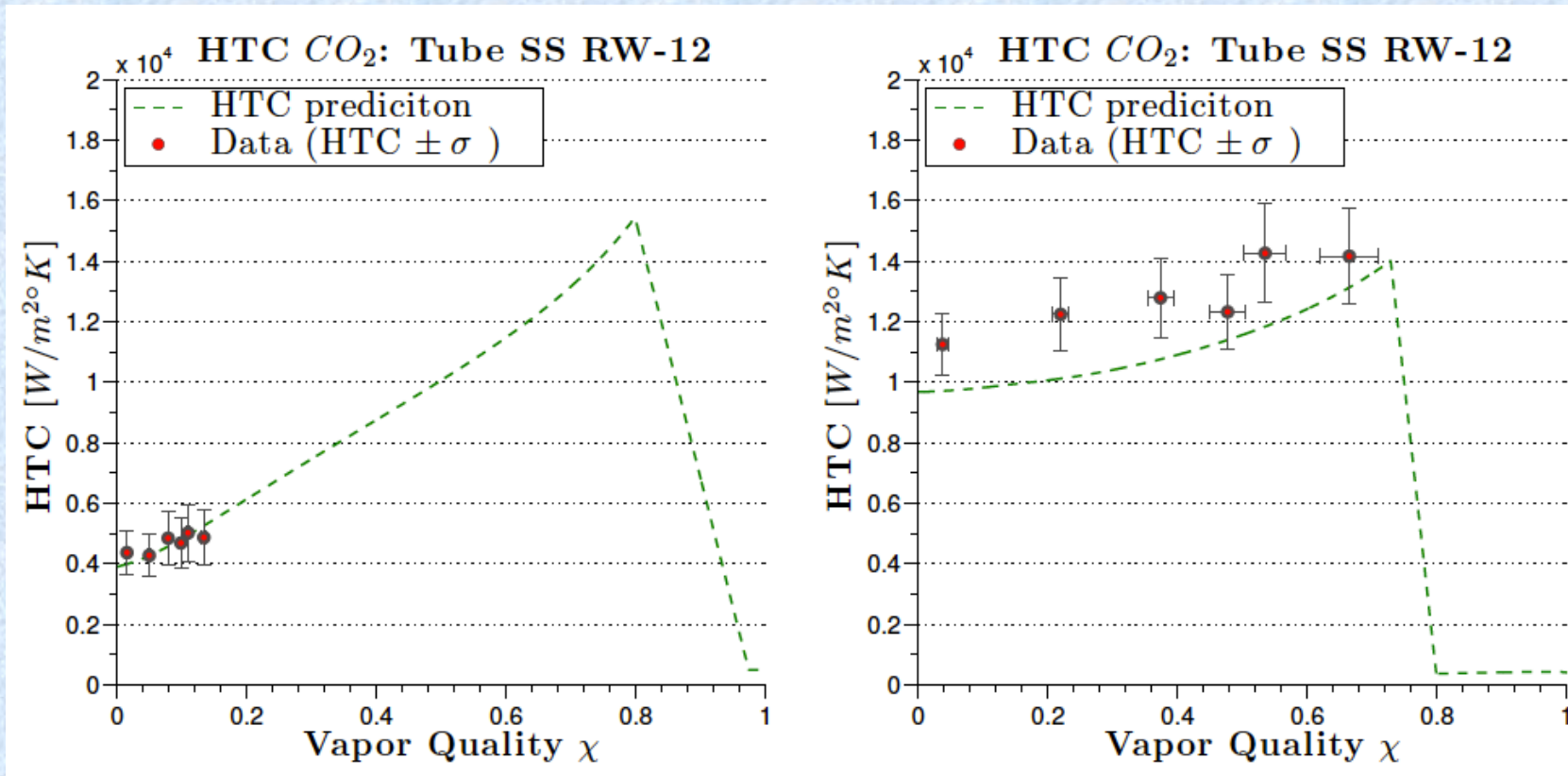
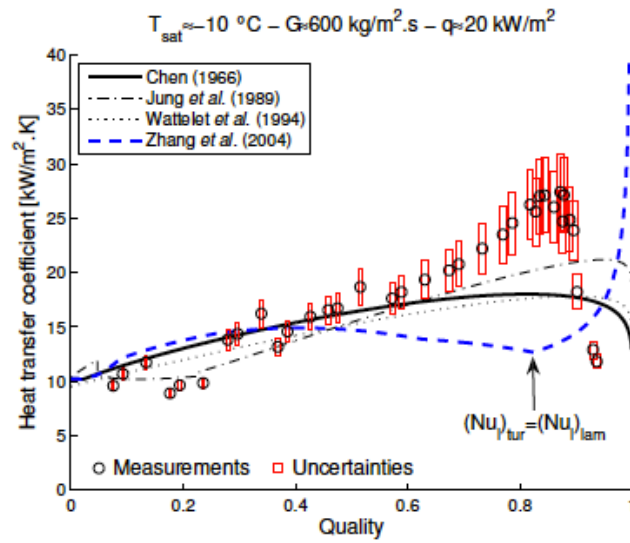


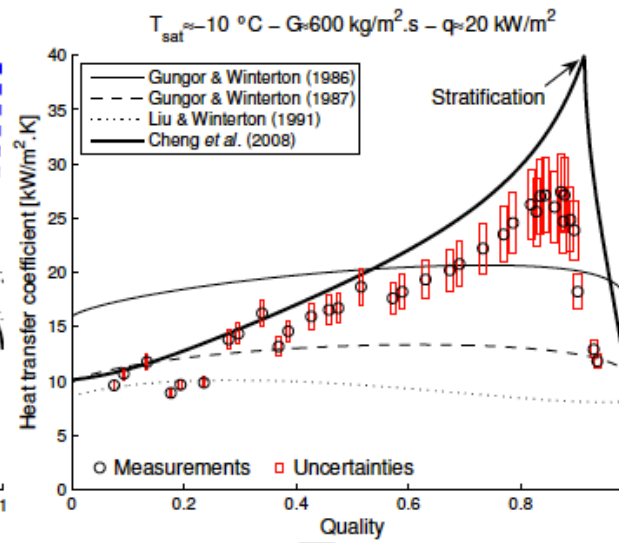
Figure 7. Simulation for 7 mm channel at following conditions: 5 kW/m², T_{sat} at 10°C and G = 200 kg/m²s with indicated value at x = 0.30.

SLAC: CO₂ Flow Boiling Tests for IBL prototype from Hemink thesis

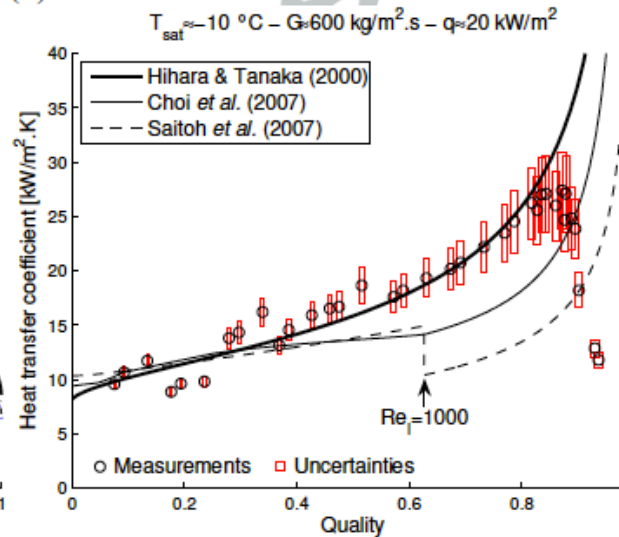
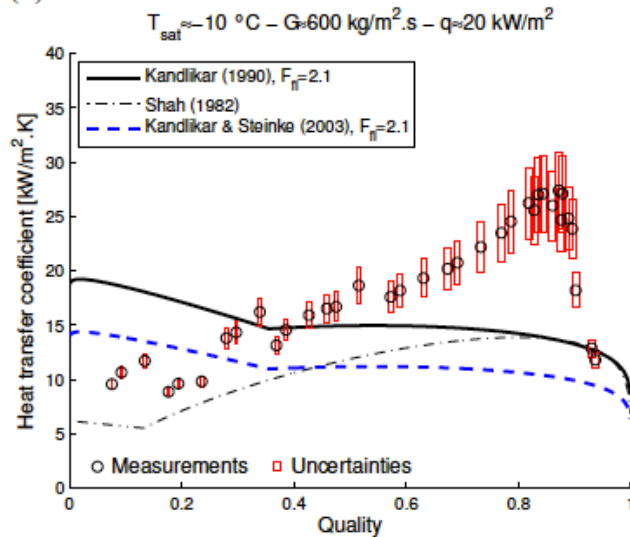




(a)



(b)



**CO₂ Flow
Boiling Tests
from
Ducoulombier
et al. in Experimental
Thermal and
Fluid Sciences
for 0.529 mm
SS tube**

CERN: CO₂ Flow Boiling Test Section Surface Roughness Value



Surface Data



Surface Statistics:

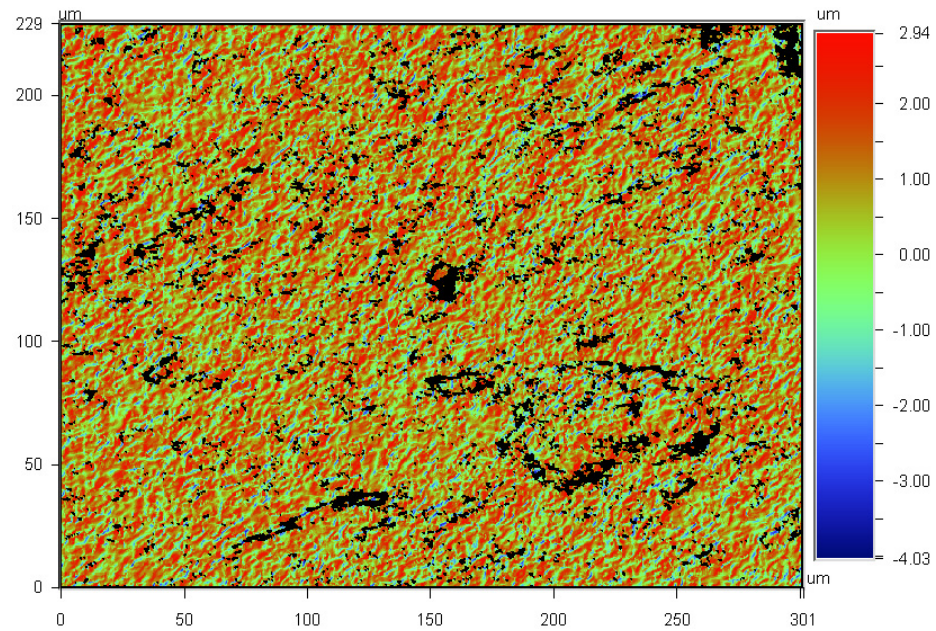
Ra: 554.82 nm
Rq: 750.13 nm
Rz:
Rt: 6.97 μm

Set-up Parameters:

Size: 736 X 480
Sampling: 410.16 nm

Processed Options:

Terms Removed:
Tilt
Filtering:
Median



Title:

Mag: 20.5 X

Date: 27/04/2010

Note:

Mode: VSI

Time: 11:11:39

CO₂ Questions:

Is CO₂ a special “maverick” fluid that requires its own special prediction methods to explain its unusual experimental trends and poor comparison to conventional methods *or not*?

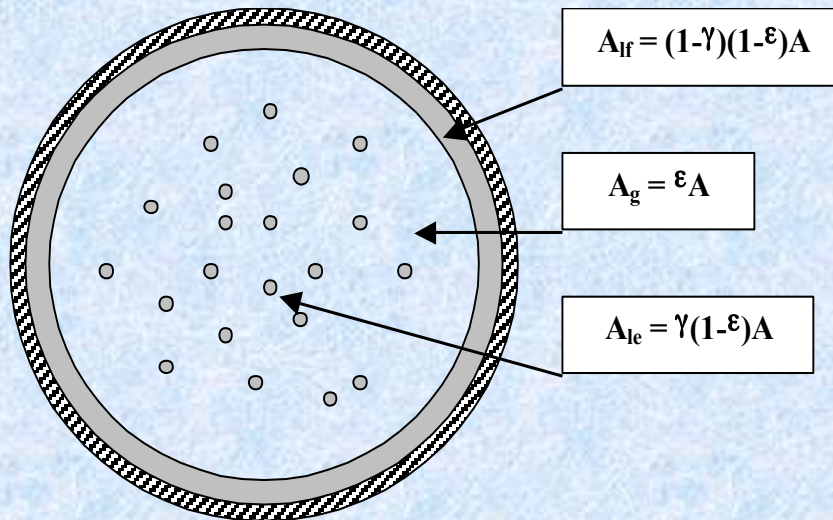
1. ...**I think NOT!** It is just beyond the range of reasonable extrapolation of conventional methods;
2. So, for now, we make special methods only applicable to CO₂;
3. In the future, high pressure data are required for other fluids in order to make one general method covering entire range of reduced pressures...we are getting high pressure data for R410A!

Biggest challenge? Predicting onset of dryout more accurately.

2nd challenge? Roughness effect on CO₂ boiling in microchannels.

VAPOR CORE EQS: OUR UNIFIED ANNULAR FLOW MODEL

Once the average liquid film thickness t is known, the core flow diameter is simply calculated as $d_c = d - 2t$, while the void fraction ε and the liquid droplet hold-up γ can be calculated from the following relations:



$$(1-\varepsilon)(1-\gamma) = \frac{t(2R-t)}{R^2}$$

$$\gamma \frac{1-\varepsilon}{\varepsilon} = e \frac{1-x}{x} \frac{\rho_g}{\rho_l}$$

The density ρ_c and the viscosity μ_c of the droplet-laden gas core are calculated as follows (ε_c is the droplet laden gas core void fraction):

$$\rho_c = (1-\varepsilon_c)\rho_l + \varepsilon_c\rho_g; \quad \mu_c = (1-\varepsilon_c)\mu_l + \varepsilon_c\mu_g \quad \varepsilon_c = \frac{\varepsilon}{\varepsilon + \gamma(1-\varepsilon)}$$

OUR UNIFIED MODEL: *NEW* CONVECTIVE BOILING

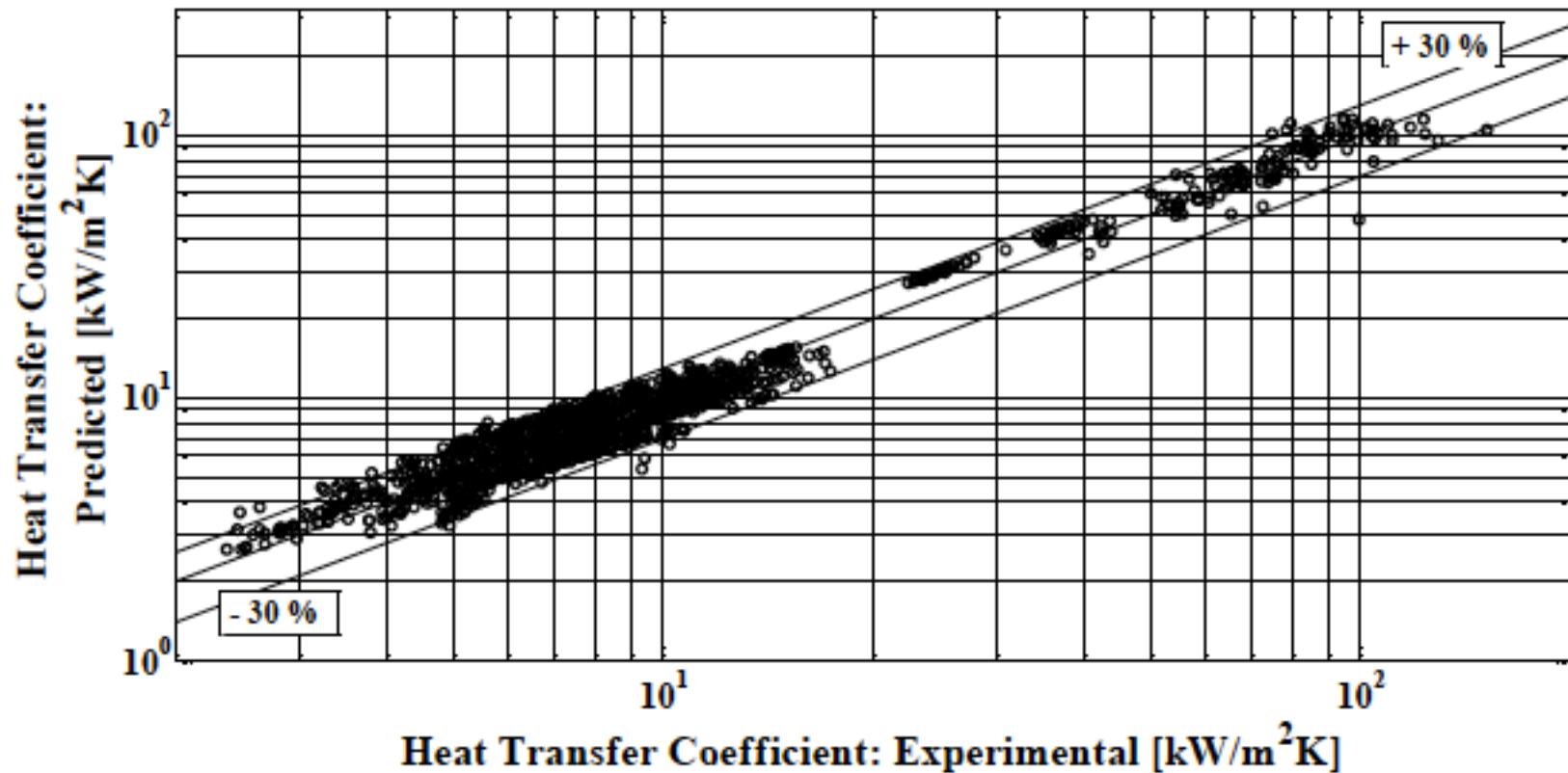
$$1 + \alpha_t^+ = \frac{ht}{k_l} = Nu = 77.6 \cdot 10^{-3} t^{+0.90} Pr_l^{0.52}; \quad 10 \leq t^+ \leq 800; \quad 0.86 \leq Pr_l \leq 6.1 \quad (27)$$

where h is the convective boiling heat transfer coefficient and Nu is a Nusselt number based on the average liquid film thickness t . As can be seen, the turbulent eddy diffusivity α_t^+ as modeled in Eq. (24) can be interpreted as a Nusselt number for the evaporating liquid film, thus providing a simple and explicit estimate of the heat transfer coefficient. Besides, as the dimensionless liquid film thickness t^+ can be interpreted as a Reynolds number for the liquid film, with the velocity wall scale V^* as characteristic velocity and the average liquid film thickness t as characteristic dimension, Eq. (27) is formally analogous to a Dittus-Boelter like heat transfer correlation. It is worth emphasizing that this method has been developed assuming no nucleate boiling occurs in the annular liquid film.

$$t^+ = \max \left(\sqrt{\frac{2\Gamma_f^+}{R^+}}, 0.066 \frac{\Gamma_f^+}{R^+} \right); \quad \frac{\Gamma_f^+}{R^+} = \frac{(1-e)(1-x)\Gamma}{2\pi\mu_l R} = (1-e)(1-x) \frac{Gd}{4\mu_l}$$

OUR UNIFIED MODEL: CONVECTIVE BOILING MODEL

Convective evaporation in annular flow: comparison to database shows no evidence of a macro-to-microchannel transition in the predictions!



OUR UNIFIED MODEL: CONVECTIVE BOILING MODEL

Convective evaporation in annular flow: simulations to illustrate unified model

